

## Three-channel, Single-phase Power/Energy IC

### Features

- Energy Data Linearity:  $\pm 0.1\%$  of Reading over 1000:1 Dynamic Range
- On-chip Functions:
  - Instantaneous Voltage, Current, and Power
  - $I_{RMS}$  and  $V_{RMS}$ , Active, Reactive, and Apparent Power
  - Current Fault and Voltage Sag Detect
  - System Calibrations / Phase Compensation
  - Temperature Sensor
  - Energy-to-pulse Conversion
  - Positive-only Accumulation Mode
- Meets Accuracy Spec for IEC, ANSI, & JIS
- Low Power Consumption
- Tamper Detection in 2-Wire Distribution Systems
- GND-referenced Signals with Single Supply
- On-chip 2.5 V Reference (25 ppm/ $^{\circ}$ C typ)
- Power Supply Monitor
- Simple Three-wire Digital Serial Interface
- "Auto-boot" Mode from Serial E<sup>2</sup>PROM.
- Power Supply Configurations  
 $VA+ = +5$  V;  $AGND = 0$  V;  $VD+ = +3.3$  V to  $+5$  V

### Description

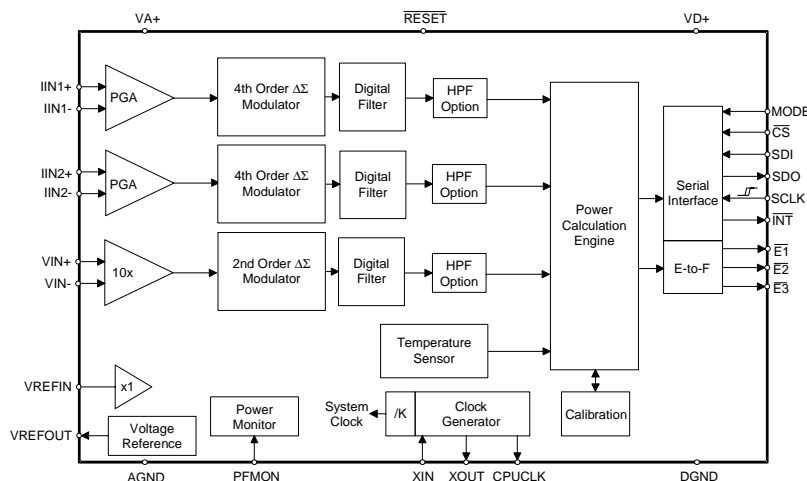
The CS5464 is an integrated power measurement device which combines three  $\Delta\Sigma$  analog-to-digital converters, power calculation engine, energy-to-frequency converter, and a serial interface on a single chip. It is designed to accurately measure instantaneous current and voltage and calculate  $V_{RMS}$ ,  $I_{RMS}$ , instantaneous power, active power, apparent power, and reactive power for high-performance power measurement applications.

The CS5464 is optimized to interface to shunt resistors or current transformers for current measurement, and to resistive dividers or potential transformers for voltage measurement.

The CS5464 features a tamper detection scheme that uses the larger of the active power measurements to register energy. Additional features include system-level calibration, temperature sensor, voltage sag & current fault detection, and phase compensation.

### ORDERING INFORMATION

See [Page 45](#).



**Preliminary Product Information**

This document contains information for a new product. Cirrus Logic reserves the right to modify this product without notice.

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## 1. OVERVIEW

The CS5464 is a CMOS monolithic power measurement device with a computation engine and an energy-to-frequency pulse output. The CS5464 combines two programmable gain amplifiers, three  $\Delta\Sigma$  analog-to-digital converters (ADCs), system calibration, and a computation engine on a single chip.

The CS5464 is designed for power measurement applications and is optimized to interface to a current-sense resistor or transformer for current measurement, and to a resistive divider or potential transformer for voltage measurement. The current channels provide programmable gains to accommodate various input levels from a multitude of sensing elements. The second current channel is designated for tamper detection support in applications where required. With a single +5 V supply on VA+/AGND, the CS5464's three input channels can accommodate common mode plus signal levels between (AGND - 0.25 V) and VA+.

The CS5464 also is equipped with a computation engine that calculates instantaneous power,  $I_{RMS}$ ,  $V_{RMS}$ , apparent power, active (real) power, reactive power, and power factor. Additional features of the CS5464 include line frequency, current and voltage sag detection, zero-cross detection, positive-only accumulation mode, and three programmable pulse output pins. To facilitate communication to a microprocessor, the CS5464 includes a simple three-wire serial interface which is SPI™ and Microwire™ compatible. The CS5464 provides three outputs for energy registration. Pins  $\overline{E1}$ ,  $\overline{E2}$ , and  $\overline{E3}$  are designed to interface to a microprocessor.

## 2. PIN DESCRIPTION

Crystal Out	<b>XOUT</b>	1 ●	28 □	<b>XIN</b>	Crystal In
CPU Clock Output	<b>CPUCLK</b>	2	27 □	<b>SDI</b>	Serial Data Input
Positive Digital Supply	<b>VD+</b>	3	26 □	<b>E2</b>	Energy Output 2
Digital Ground	<b>DGND</b>	4	25 □	<b>E1</b>	Energy Output 1
Serial Clock	<b>SCLK</b>	5	24 □	<b>INT</b>	Interrupt
Serial Data Output	<b>SDO</b>	6	23 □	<b>RESET</b>	Reset
Chip Select	<b>CS</b>	7	22 □	<b>E3</b>	Energy Output 3
Mode Select	<b>MODE</b>	8	21 □	<b>PFMON</b>	Power Fail Monitor
Differential Voltage Input	<b>VIN+</b>	9	20 □	<b>IIN+</b>	Differential Current Input
Differential Voltage Input	<b>VIN-</b>	10	19 □	<b>IIN-</b>	Differential Current Input
Voltage Reference Output	<b>VREFOUT</b>	11	18 □	<b>VA+</b>	Positive Analog Supply
Voltage Reference Input	<b>VREFIN</b>	12	17 □	<b>AGND</b>	Analog Ground
Factory Test	<b>TEST1</b>	13	16 □	<b>IIN2+</b>	Differential Current Input
Factory Test	<b>TEST2</b>	14	15 □	<b>IIN2-</b>	Differential Current Input

### Clock Generator

<b>Crystal Out</b>	1,28	<b>XOUT, XIN</b> - The output and input of an inverting amplifier. Oscillation occurs when connected to a crystal, providing an on-chip system clock. Alternatively, an external clock can be supplied to the XIN pin to provide the system clock for the device.
<b>Crystal In</b>		
<b>CPU Clock Output</b>	2	<b>CPUCLK</b> - Output of on-chip oscillator which can drive one standard CMOS load.

### Control Pins and Serial Data I/O

<b>Serial Clock Input</b>	5	<b>SCLK</b> - A Schmitt Trigger input pin. Clocks data from the SDI pin into the receive buffer and out of the transmit buffer onto the SDO pin when $\overline{CS}$ is low.
<b>Serial Data Output</b>	6	<b>SDO</b> - Serial port data output pin. SDO is forced into a high impedance state when $\overline{CS}$ is high.
<b>Chip Select</b>	7	$\overline{CS}$ - Low, activates the serial port interface.
<b>Mode Select</b>	8	<b>MODE</b> - High, enables the "auto-boot" mode. The mode pin is pull-down by an internal resistor.
<b>Energy Output</b>	22, 25, 26	$\overline{E3}, \overline{E1}, \overline{E2}$ - Active low pulses with an output frequency proportional to energy.
<b>Reset</b>	23	$\overline{RESET}$ - A Schmitt Trigger input pin. Low activates Reset, all internal registers (some of which drive output pins) are set to their default states.
<b>Interrupt</b>	24	$\overline{INT}$ - Low, indicates that an enabled event has occurred.
<b>Serial Data Input</b>	27	<b>SDI</b> - Serial port data input pin. Data will be input at a rate determined by SCLK.

### Analog Inputs/Outputs

<b>Differential Voltage Inputs</b>	9,10	<b>VIN+, VIN-</b> - Differential analog input pins for the voltage channel.
<b>Differential Current Inputs</b>	19,20, 15,16	<b>IIN+, IIN-, IIN2+, IIN2-</b> - Differential analog input pins for the current channel.
<b>Voltage Reference Output</b>	11	<b>VREFOUT</b> - The on-chip voltage reference output. The voltage reference has a nominal magnitude of 2.5 V and is referenced to the AGND pin on the converter.
<b>Voltage Reference Input</b>	12	<b>VREFIN</b> - The input to this pin establishes the voltage reference for the on-chip modulator.

### Power Supply Connections

<b>Positive Digital Supply</b>	3	<b>VD+</b> - The positive digital supply.
<b>Digital Ground</b>	4	<b>DGND</b> - Digital Ground.
<b>Positive Analog Supply</b>	18	<b>VA+</b> - The positive analog supply.
<b>Analog Ground</b>	17	<b>AGND</b> - Analog ground.
<b>Power Fail Monitor</b>	21	<b>PFMON</b> - The power fail monitor pin monitors the analog supply. If PFMON's voltage threshold is tripped, a Low-Supply Detect (LSD) event is set in the status register.

### Test Connections

<b>Factory Test</b>	13,14	<b>TEST1, TEST2</b> - Factory use only. Connect to AGND.
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### 3. CHARACTERISTICS & SPECIFICATIONS

#### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit
Positive Digital Power Supply	VD+	3.135	5.0	5.25	V
Positive Analog Power Supply	VA+	4.75	5.0	5.25	V
Voltage Reference	VREFIN	-	2.5	-	V
Specified Temperature Range	T <sub>A</sub>	-40	-	+85	°C

#### ANALOG CHARACTERISTICS

- Min / Max characteristics and specifications are guaranteed over all Recommended Operating Conditions.
- Typical characteristics and specifications are measured at nominal supply voltages and T<sub>A</sub> = 25 °C.
- VA+ = VD+ = 5 V ±5%; AGND = DGND = 0 V; VREFIN = +2.5 V. All voltages with respect to 0 V.
- MCLK = 4.096 MHz.

Parameter	Symbol	Min	Typ	Max	Unit
<b>Accuracy</b>					
Active Power (Note 1)	P <sub>Active</sub>	-	±0.1	-	%
Average Reactive Power (Note 1 and 2)	Q <sub>Avg</sub>	-	±0.2	-	%
Power Factor (Note 1 and 2)	PF	-	±0.2 ±0.27	-	%
Current RMS (Note 1)	I <sub>RMS</sub>	-	±0.1 ±0.17	-	%
Voltage RMS (Note 1)	V <sub>RMS</sub>	-	±0.1	-	%
<b>Analog Inputs (All Channels)</b>					
Common Mode Rejection (DC, 50, 60 Hz)	CMRR	80	-	-	dB
Common Mode + Signal		-0.25	-	VA+	V
<b>Analog Inputs (Current Channels)</b>					
Differential Input Range [(IIN+) - (IIN-)]	IIN	-	500 100	-	mV <sub>P-P</sub> mV <sub>P-P</sub>
Total Harmonic Distortion	THD	80	94	-	dB
Crosstalk with Voltage Channel at Full Scale (50, 60 Hz)		-	-115	-	dB
Input Capacitance	IC	-	27	-	pF
Effective Input Impedance	EII	30	-	-	kΩ
Noise (Referred to Input)	N <sub>I</sub>	-	-	22.5 4.5	μV <sub>rms</sub> μV <sub>rms</sub>
Offset Drift (Without the High Pass Filter)	OD	-	4.0	-	μV/°C
Gain Error (Note 3)	GE	-	±0.4	-	%

Notes: 1. Applies when the HPF option is enabled.

2. Applies when the line frequency is equal to the product of the Output Word Rate (OWR) and the value of epsilon (ε).

**ANALOG CHARACTERISTICS** (Continued)

Parameter	Symbol	Min	Typ	Max	Unit	
<b>Analog Inputs (Voltage Channel)</b>						
Differential Input Range	[(VIN+) - (VIN-)]	VIN	-	500	-	mV <sub>P-P</sub>
Total Harmonic Distortion		THD	65	75	-	dB
Crosstalk with Current Channel at Full Scale (50, 60 Hz)			-	-70	-	dB
Input Capacitance	All Gain Ranges	IC	-	2.0	-	pF
Effective Input Impedance		EII	2	-	-	MΩ
Noise (Referred to Input)		N <sub>V</sub>	-	-	140	μV <sub>rms</sub>
Offset Drift (Without the High Pass Filter)		OD	-	16.0	-	μV/°C
Gain Error	(Note 3)	GE	-	±3.0		%
<b>Temperature Channel</b>						
Temperature Accuracy		T	-	±5	-	°C
<b>Power Supplies</b>						
Power Supply Currents (Active State)	I <sub>A+</sub>	PSCA	-	1.3	-	mA
	I <sub>D+</sub> (VA+ = VD+ = 5 V)	PSCD	-	2.9	-	mA
	I <sub>D+</sub> (VA+ = 5 V, VD+ = 3.3 V)	PSCD	-	1.7	-	mA
Power Consumption (Note 4)	Active State (VA+ = VD+ = 5 V)	PC	-	33	36	mW
	Active State (VA+ = 5 V, VD+ = 3.3 V)		-	20	23	mW
	Stand-by State		-	7	-	mW
	Sleep State		-	10	-	uW
Power Supply Rejection Ratio (50, 60 Hz) (Note 5)	Voltage Channel	PSRR	48	55	-	dB
	Current Channel (Gain = 50x)		68	75	-	dB
	Current Channel (Gain = 10x)		60	65	-	dB
PFMON Low-voltage Trigger Threshold	(Note 6)	PMLO	2.3	2.45	-	V
PFMON High-voltage Power-on Trip Point	(Note 7)	PMHI	-	2.55	2.7	V

Notes: 3. Applies before system calibration.

4. All outputs unloaded. All inputs CMOS level.

5. Measurement method for PSRR: VREFIN tied to VREFOUT, VA+ = VD+ = 5 V, a 150 mV (zero-to-peak) (60 Hz) sinewave is imposed onto the +5 V DC supply voltage at VA+ and VD+ pins. The "+" and "-" input pins of both input channels are shorted to AGND. The CS5464 is then commanded to continuous conversion acquisition mode, and digital output data is collected for the channel under test. The (zero-to-peak) value of the digital sinusoidal output signal is determined, and this value is converted into the (zero-to-peak) value of the sinusoidal voltage (measured in mV) that would need to be applied at the channel's inputs, in order to cause the same digital sinusoidal output. This voltage is then defined as V<sub>eq</sub>. PSRR is (in dB):

$$PSRR = 20 \cdot \log \left[ \frac{150}{V_{eq}} \right]$$

6. When voltage level on PFMON is sagging, and LSD bit = 0, the voltage at which LSD is set to 1.

7. If the LSD bit has been set to 1 (because PFMON voltage fell below PMLO), this is the voltage level on PFMON at which the LSD bit can be permanently reset back to 0.



**VOLTAGE REFERENCE**

Parameter	Symbol	Min	Typ	Max	Unit
<b>Reference Output</b>					
Output Voltage	VREFOUT	+2.4	+2.5	+2.6	V
Temperature Coefficient (Note 8)	TC <sub>VREF</sub>	-	25	60	ppm/°C
Load Regulation (Note 9)	ΔV <sub>R</sub>	-	6	10	mV
<b>Reference Input</b>					
Input Voltage Range	VREFIN	+2.4	+2.5	+2.6	V
Input Capacitance		-	4	-	pF
Input CVF Current		-	100	-	nA

Notes: 8. The voltage at VREFOUT is measured across the temperature range. From these measurements the following formula is used to calculate the VREFOUT Temperature Coefficient:

$$TC_{VREF} = \left( \frac{VREFOUT_{MAX} - VREFOUT_{MIN}}{VREFOUT_{AVG}} \right) \left( \frac{1}{T_{A_{MAX}} - T_{A_{MIN}}} \right) (1.0 \times 10^6)$$

9. Specified at maximum recommended output of 1 μA, source or sink.

**DIGITAL CHARACTERISTICS**

- Min / Max characteristics and specifications are guaranteed over all Recommended Operating Conditions.
- Typical characteristics and specifications are measured at nominal supply voltages and TA = 25 °C.
- VA+ = VD+ = 5V ±5%; AGND = DGND = 0 V. All voltages with respect to 0 V.
- MCLK = 4.096 MHz.

Parameter	Symbol	Min	Typ	Max	Unit
<b>Master Clock Characteristics</b>					
Master Clock Frequency Internal Gate Oscillator (Note 11)	MCLK	2.5	4.096	20	MHz
Master Clock Duty Cycle		40	-	60	%
CPUCLK Duty Cycle (Note 12 and 13)		40	-	60	%
<b>Filter Characteristics</b>					
Phase Compensation Range (Voltage Channel, 60 Hz)		-2.8	-	+2.8	°
Input Sampling Rate DCLK = MCLK/K		-	DCLK/8	-	Hz
Digital Filter Output Word Rate (Both Channels)	OWR	-	DCLK/1024	-	Hz
High-pass Filter Corner Frequency -3 dB		-	0.5	-	Hz
Full-scale DC Calibration Range (Referred to Input) (Note 14)	FSCR	25	-	100	%F.S.
Channel-to-channel Time-shift Error (Note 15)			1.0		μs
<b>Input/Output Characteristics</b>					
High-level Input Voltage All Pins Except XIN and SCLK and $\overline{\text{RESET}}$ XIN SCLK and $\overline{\text{RESET}}$	V <sub>IH</sub>	0.6 VD+ (VD+) - 0.5 0.8 VD+	- - -	- - -	V V V
Low-level Input Voltage (VD = 5 V) All Pins Except XIN and SCLK and $\overline{\text{RESET}}$ XIN SCLK and $\overline{\text{RESET}}$	V <sub>IL</sub>	- - -	- - -	0.8 1.5 0.2 VD+	V V V

Parameter	Symbol	Min	Typ	Max	Unit
Low-level Input Voltage (VD = 3.3 V) All Pins Except XIN and SCLK and $\overline{\text{RESET}}$ XIN SCLK and $\overline{\text{RESET}}$	$V_{IL}$	- - -	- - -	0.48 0.3 0.2 VD+	V V V
High-level Output Voltage $I_{out} = +5 \text{ mA}$	$V_{OH}$	(VD+) - 1.0	-	-	V
Low-level Output Voltage $I_{out} = -5 \text{ mA (VD = +5V)}$ $I_{out} = -2.5 \text{ mA (VD = +3.3V)}$	$V_{OL}$	- -	- -	0.4 0.4	V V
Input Leakage Current (Note 16)	$I_{in}$	-	$\pm 1$	$\pm 10$	$\mu\text{A}$
3-state Leakage Current	$I_{OZ}$	-	-	$\pm 10$	$\mu\text{A}$
Digital Output Pin Capacitance	$C_{out}$	-	5	-	pF

Notes: 10. All measurements performed under static conditions.

11. If a crystal is used, XIN frequency must remain between 2.5 MHz - 5.0 MHz. If an external oscillator is used, XIN frequency range is 2.5 MHz - 20 MHz, but K must be set so that MCLK is between 2.5 MHz - 5.0 MHz.
12. If external MCLK is used, the duty cycle must be between 45% and 55% to maintain this specification.
13. The frequency of CPUCLK is equal to MCLK.
14. The minimum FSCR is limited by the maximum allowed gain register value. The maximum FSCR is limited by the full-scale signal applied to the channel input.
15. Configuration Register bits PC[6:0] are set to "0000000".
16. The MODE pin is pulled low by an internal resistor.

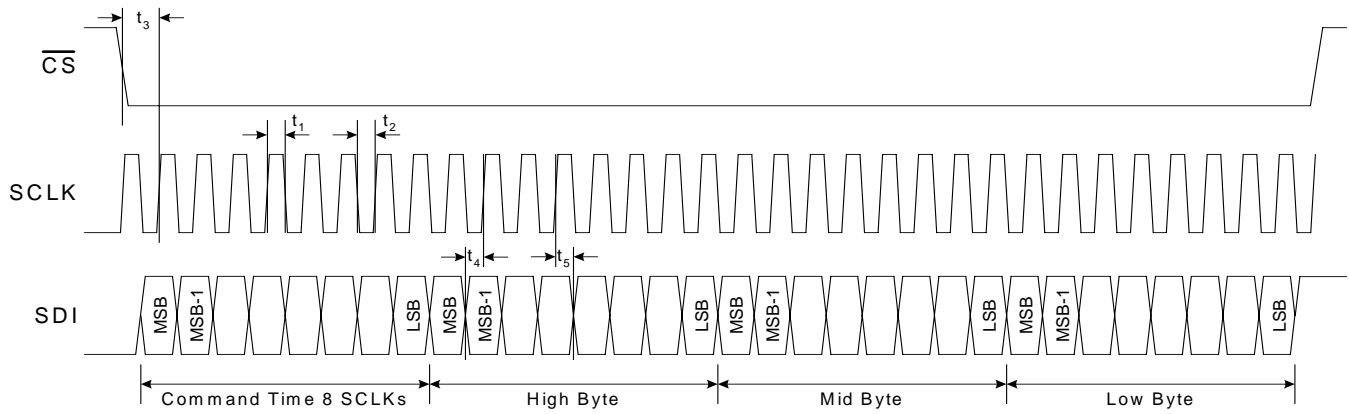
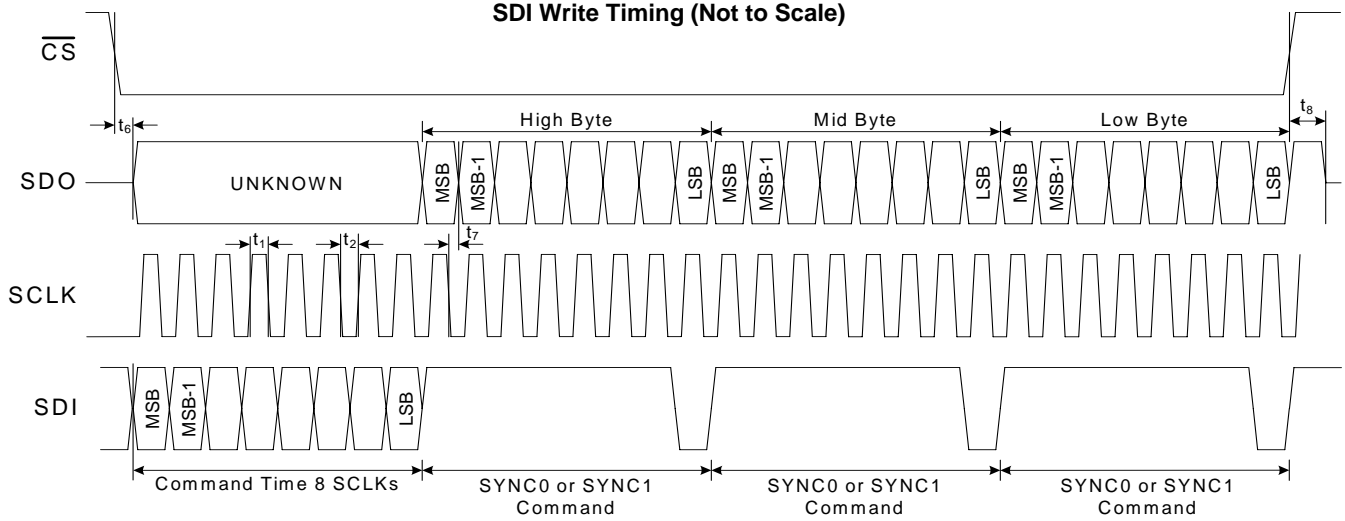
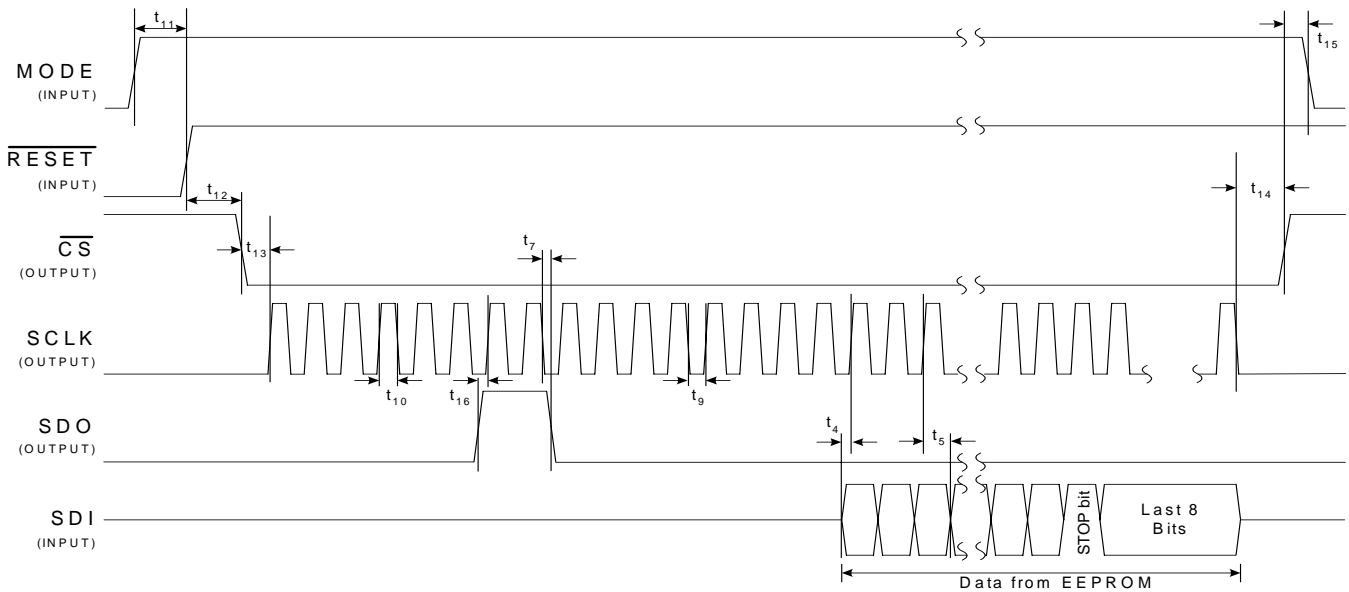
**SWITCHING CHARACTERISTICS**

- Min / Max characteristics and specifications are guaranteed over all Recommended Operating Conditions.
- Typical characteristics and specifications are measured at nominal supply voltages and TA = 25 °C.
- VA+ = 5 V ±5% VD+ = 3.3 V ±5% or 5 V ±5%; AGND = DGND = 0 V. All voltages with respect to 0 V.
- Logic Levels: Logic 0 = 0 V, Logic 1 = VD+.

Parameter	Symbol	Min	Typ	Max	Unit	
Rise Times (Note 16)	$t_{rise}$	-	-	1.0	$\mu s$	
Any Digital Output		-	50	-	ns	
Fall Times (Note 16)	$t_{fall}$	-	-	1.0	$\mu s$	
Any Digital Output		-	50	-	ns	
<b>Start-up</b>						
Oscillator Start-up Time	XTAL = 4.096 MHz (Note 17)	$t_{ost}$	-	60	-	ms
<b>Serial Port Timing</b>						
Serial Clock Frequency	SCLK	-	-	2	MHz	
Serial Clock	Pulse Width High	$t_1$	200	-	-	ns
	Pulse Width Low	$t_2$	200	-	-	ns
<b>SDI Timing</b>						
CS Falling to SCLK Rising	$t_3$	50	-	-	ns	
Data Set-up Time Prior to SCLK Rising	$t_4$	50	-	-	ns	
Data Hold Time After SCLK Rising	$t_5$	100	-	-	ns	
<b>SDO Timing</b>						
CS Falling to SDO Driving	$t_6$	-	20	50	ns	
SCLK Falling to New Data Bit (hold time)	$t_7$	-	20	50	ns	
CS Rising to SDO Hi-Z	$t_8$	-	20	50	ns	
<b>Auto-Boot Timing</b>						
Serial Clock	Pulse Width Low	$t_9$		8	MCLK	
	Pulse Width High	$t_{10}$		8	MCLK	
MODE setup time to RESET Rising	$t_{11}$	50			ns	
RESET rising to CS falling	$t_{12}$	48			MCLK	
CS falling to SCLK rising	$t_{13}$	100	8		MCLK	
SCLK falling to CS rising	$t_{14}$		16		MCLK	
CS rising to driving MODE low (to end auto-boot sequence)	$t_{15}$	50			ns	
SDO guaranteed setup time to SCLK rising	$t_{16}$	100			ns	

Notes: 16. Specified using 10% and 90% points on waveform of interest. Output loaded with 50 pF.

17. Oscillator start-up time varies with crystal parameters. This specification does not apply when using an external clock source.

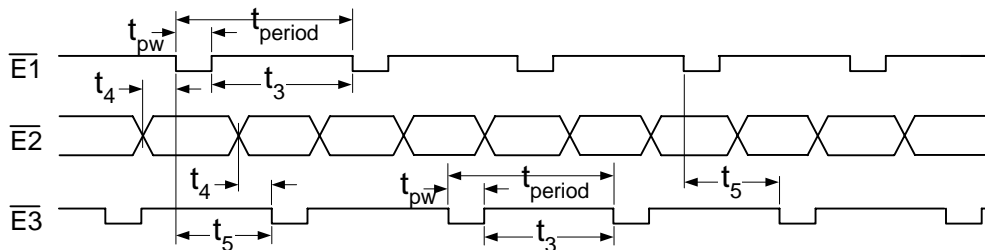

**SDI Write Timing (Not to Scale)**

**SDO Read Timing (Not to Scale)**

**Auto-boot Sequence Timing (Not to Scale)**
**Figure 1. CS5464 Read and Write Timing Diagrams**

**SWITCHING CHARACTERISTICS** (Continued)

Parameter	Symbol	Min	Typ	Max	Unit
<b><math>\overline{E1}</math>, <math>\overline{E2}</math>, and <math>\overline{E3}</math> Timing</b> (Note 18 and 19)					
Period	$t_{\text{period}}$	250	-	-	$\mu\text{s}$
Pulse Width	$t_{\text{pw}}$	244	-	-	$\mu\text{s}$
Rising Edge to Falling Edge	$t_3$	6	-	-	$\mu\text{s}$
$\overline{E2}$ Setup to $\overline{E1}$ and/or $\overline{E3}$ Falling Edge	$t_4$	1.5	-	-	$\mu\text{s}$
$\overline{E1}$ Falling Edge to $\overline{E3}$ Falling Edge	$t_5$	248	-	-	$\mu\text{s}$

Notes: 18. Pulse output timing is specified at MCLK = 4.096 MHz, E2MODE = 0, and E3MODE[1:0] = 0. Refer to [5.5 Energy Pulse Output](#) on page 18 for more information on pulse output pins.

19. Timing is proportional to the frequency of MCLK.



**Figure 2. Timing Diagram for  $\overline{E1}$ ,  $\overline{E2}$ , and  $\overline{E3}$**

**ABSOLUTE MAXIMUM RATINGS**

WARNING: Operation at or beyond these limits may result in permanent damage to the device.

Normal operation is not guaranteed at these extremes.

Parameter	Symbol	Min	Typ	Max	Unit
DC Power Supplies					
(Notes 20 and 21) Positive Digital	VD+	-0.3	-	+6.0	V
Positive Analog	VA+	-0.3	-	+6.0	V
Input Current, Any Pin Except Supplies	$I_{\text{IN}}$	-	-	$\pm 10$	mA
Output Current, Any Pin Except VREFOUT	$I_{\text{OUT}}$	-	-	100	mA
Power Dissipation	$P_{\text{D}}$	-	-	500	mW
Analog Input Voltage	$V_{\text{INA}}$	- 0.3	-	(VA+) + 0.3	V
Digital Input Voltage	$V_{\text{IND}}$	-0.3	-	(VD+) + 0.3	V
Ambient Operating Temperature	$T_{\text{A}}$	-40	-	85	$^{\circ}\text{C}$
Storage Temperature	$T_{\text{stg}}$	-65	-	150	$^{\circ}\text{C}$

Notes: 20. VA+ and AGND must satisfy  $[(\text{VA}+) - (\text{AGND})] \leq + 6.0 \text{ V}$ .

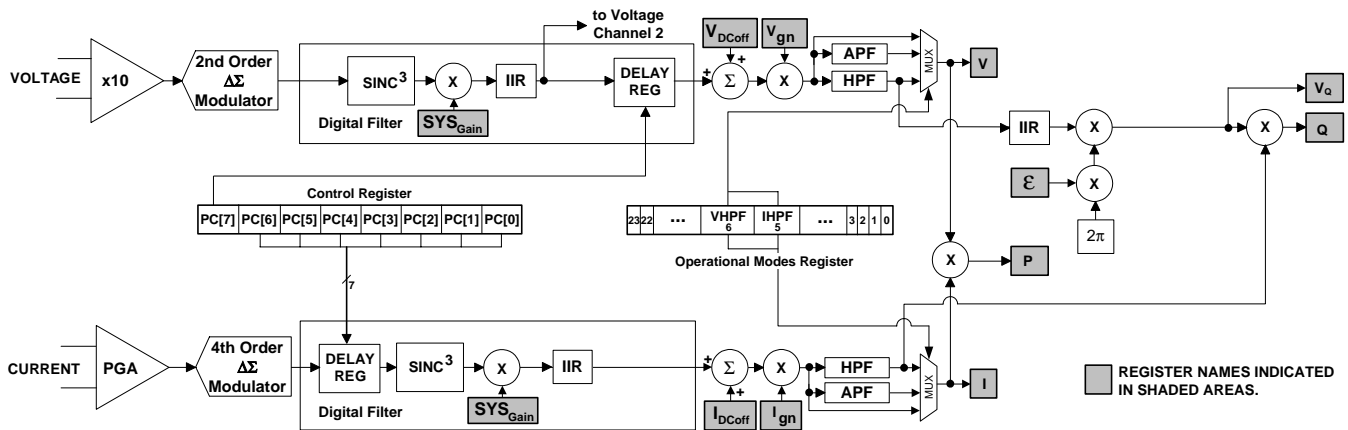
21. VD+ and AGND must satisfy  $[(\text{VD}+) - (\text{AGND})] \leq + 6.0 \text{ V}$ .

22. Applies to all pins including continuous over-voltage conditions at the analog input pins.

23. Transient current of up to 100 mA will not cause SCR latch-up.

24. Maximum DC input current for a power supply pin is  $\pm 50 \text{ mA}$ .

25. Total power dissipation, including all input currents and output currents.



**Figure 3. Data Measurement Flow Diagram**

## 4. THEORY OF OPERATION

The CS5464 is a four-channel analog-to-digital converter (ADC) followed by a computation engine that performs power calculations and energy-to-pulse conversion. The data flow for the voltage and current channel measurement and the power calculation algorithms are depicted in Figures 3, 4, and 5.

The CS5464 analog inputs are structured with two *Current* channels and two *Voltage* channels, then optimized to simplify interfacing various sensing elements. As shown in Figures 3 and 4, the current channels are fully independent while the two voltage channels are multiplexed.

The voltage-sensing element introduces a voltage waveform on the voltage channel input  $V_{IN\pm}$  and is subject to a gain of 10x. A second-order delta-sigma modulator samples the amplified signal for digitization.

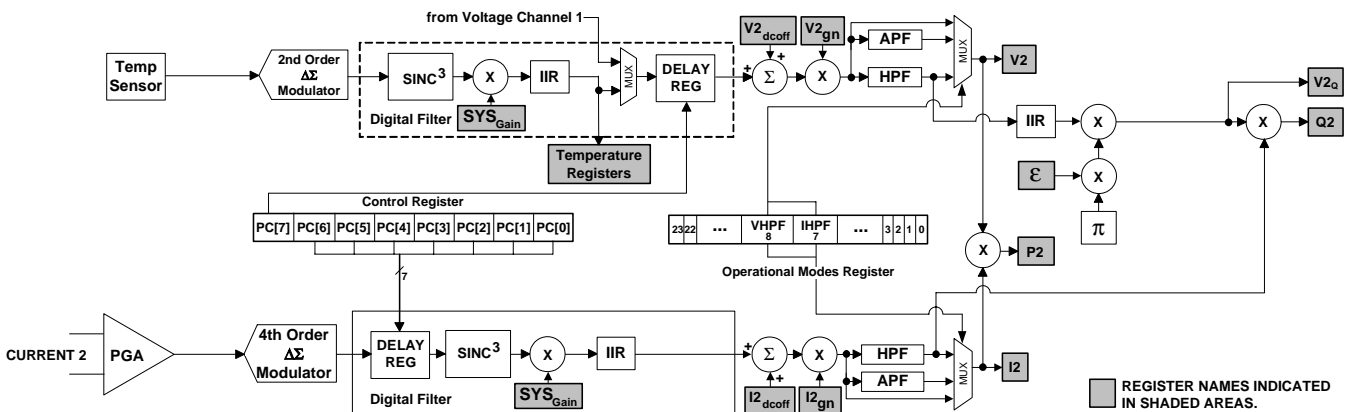
Simultaneously, the current-sensing elements introduce a voltage waveform on the two current channel inputs  $I_{IN\pm}$  and  $I_{IN2\pm}$ , which is subject to the two selectable gains of the programmable gain amplifier (PGA). The

amplified signals are sampled by a fourth-order delta-sigma modulator for digitization. The converters sample at a rate of  $MCLK/8$ . The over-sampling provides a wide dynamic range and simplified anti-alias filter design.

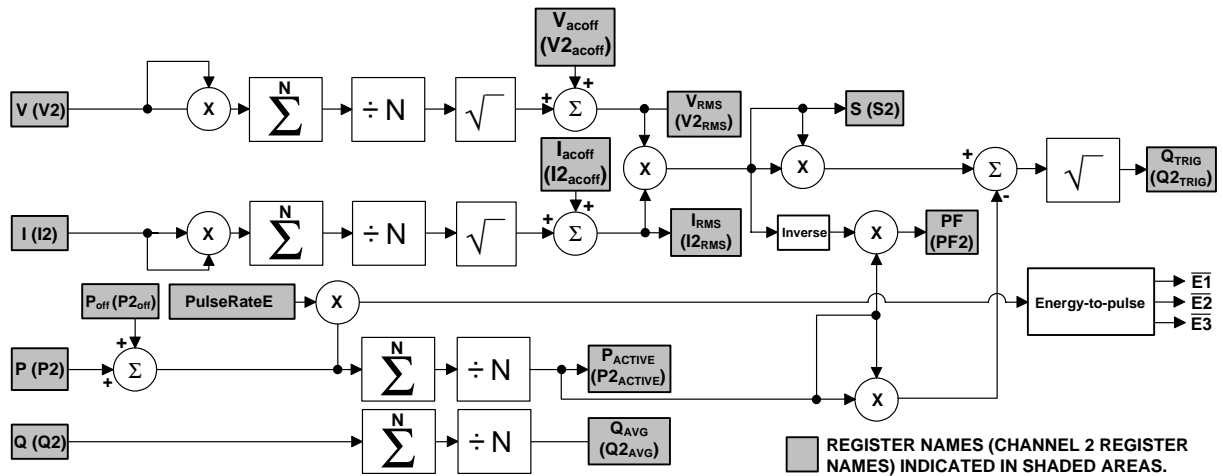
### 4.1 Digital Filters

The decimating digital filters on the four channels are  $Sinc^3$  filters followed by 4th-order IIR filters. The single-bit data is passed to the low-pass decimation filter and output at a fixed word rate. The output word is passed to an IIR filter to compensate for the magnitude roll off of the low-pass filtering operation.

An optional digital high-pass filter (*HPF* in Figures 3 and 4) removes any DC component from the selected signal path. By removing the DC component from the voltage and/or the current channel, any DC content will also be removed from the calculated active power as well. With both HPFs enabled the DC component will be removed



**Figure 4. Data Measurement Flow Diagram**



**Figure 5. Power Calculation Flow**

from the calculated  $V_{RMS}$  and  $I_{RMS}$  as well as the apparent power.

When the optional HPF in either channel is disabled, an all-pass filter (APF) in the complement channel is implemented. The APF has an amplitude response that is flat within the channel bandwidth and is used for matching phase in systems where only one channel's HPF is engaged. For more information, see [5.3 High-pass Filters](#) on page 17.

## 4.2 Voltage and Current Measurements

The digital filter output word is subject to a DC offset adjustment and a gain calibration (See [Section 7. System Calibration](#) on page 39). The calibrated measurement is available by reading the instantaneous voltage and current registers.

The Root Mean Square (*RMS* in [Figure 5](#)) calculations are performed on  $N$  instantaneous voltage and current samples,  $V_n$  and  $I_n$ , respectively (where  $N$  is the cycle count), using the formula:

$$I_{RMS} = \sqrt{\frac{\sum_{n=0}^{N-1} I_n^2}{N}}$$

and likewise for  $V_{RMS}$ , using  $V_n$ .  $I_{RMS}$  and  $V_{RMS}$  are accessible by register reads, which are updated once every cycle count (referred to as a computational cycle).

## 4.3 Power Measurements

The instantaneous voltage and current samples are multiplied to obtain the instantaneous power (see [Figure 3](#) and [4](#)). The product is then averaged over  $N$  conversions to compute active power and is used to drive energy pulse output  $\bar{E}1$ . Energy output  $\bar{E}2$  is configurable and can provide an energy sign, a pulse output that is proportional to the apparent power, or a tamper indicator. Energy output  $\bar{E}3$  provides a pulse output that is proportional to the reactive power or the apparent power. Output  $\bar{E}3$  can also be set to indicate the PFMON comparator output or to indicate the sign of the voltage applied to the voltage channel.

The apparent power ( $S$ ,  $S2$ ) is the combination of the active power and reactive power, without reference to an impedance phase angle, and is calculated by the CS5464 using the following formula:

$$S = V_{RMS} \times I_{RMS}$$

Power Factor ( $PF$ ,  $PF2$ ) is the active power ( $P_{Active}$ ,  $P2_{Active}$ ) divided by the apparent power ( $S$ ,  $S2$ )

$$PF = \frac{P_{Active}}{S}$$

The sign of the power factor is determined by the active power.

The CS5464 calculates the reactive power ( $Q_{Trig}$ ,  $Q2_{Trig}$ ) utilizing trigonometric identities, using the formula

$$Q_{Trig} = \sqrt{S^2 - P_{Active}^2}$$

The average reactive power calculation ( $Q_{AVg}$ ,  $Q2_{AVg}$ ) is generated by averaging the voltage then multiplying that value by the current measurement with a  $90^\circ$  phase difference between the two. The  $90^\circ$  phase shift is realized by applying an IIR digital filter in the voltage channel to obtain quadrature voltage (see [Figure 3](#) and [4](#)). This filter will give exactly  $-90^\circ$  phase shift across all frequencies, and utilizes epsilon ( $\epsilon$ ) to achieve unity gain at the line frequency.

The instantaneous quadrature voltage ( $V_Q$ ,  $V2_Q$ ) and current ( $I$ ,  $I2$ ) samples are multiplied to obtain the instantaneous quadrature power ( $Q$ ,  $Q2$ ). The product is then averaged over  $N$  conversions, utilizing the formula

$$Q_{AVg} = \frac{\sum_{n=1}^N Q_n}{N}$$

The peak current ( $I_{peak}$ ,  $I2_{peak}$ ) and peak voltage ( $V_{peak}$ ,  $V2_{peak}$ ) are the instantaneous current and voltage, respectively, with the greatest magnitude detected during the previous computation cycle. Active, apparent, reactive, and fundamental power are updated every computation cycle.

#### 4.4 Tamper Detection

The third channel (inputs  $IIN2\pm$ ) can be used for tamper detection when required by the application. Typically using a shunt resistor to save cost, the tamper input monitors the current through the neutral connection. See [Figure 19](#) on page 43.

The CS5464 calculates active power,  $P$  and  $P2$ , using current channel inputs,  $IIN\pm$  and  $IIN2\pm$ , respectively. The active powers are then compared, looking for deviations greater than a programmable threshold, as an indicator of a connection fault, potentially caused by tampering. When tamper detect is enabled (by default) the current channel that produces the larger active power will be registered in the pulse output accumulation registers and pulse output pins.

#### 4.5 Linearity Performance

The linearity of the  $V_{RMS}$ ,  $I_{RMS}$ , active, reactive, and power-factor power measurements (before calibration) will be within  $\pm 0.1\%$  of reading over the ranges specified, with respect to the input voltage levels required to cause full-scale readings in the  $I_{RMS}$  and  $V_{RMS}$  registers. Refer to [Accuracy Specifications](#) on page 7.

Until the CS5464 is calibrated, the *accuracy* of the CS5464 (with respect to a reference line-voltage and line-current level on the power mains) is not guaranteed to within  $\pm 0.1\%$ . (See [Section 7. System Calibration](#) on page 39.) The accuracy of the internal calculations can often be improved by selecting a value for the Cycle Count Register that will cause the time duration of one computation cycle to be equal to (or very close to) a whole number of power-line cycles (and  $N$  must be 4000 or greater).



## 5. FUNCTIONAL DESCRIPTION

### 5.1 Analog Inputs

The CS5464 is equipped with three fully differential input channels. The inputs  $V_{IN\pm}$ ,  $I_{IN\pm}$ , and  $I_{IN2\pm}$  are designated as the voltage, current, and current 2 channel inputs, respectively. The full-scale differential input voltage for the current and voltage channel is  $\pm 250\text{ mV}_P$ .

#### 5.1.1 Voltage Channel Input

The output of the line voltage resistive divider or transformer is connected to the  $V_{IN+}$  and  $V_{IN-}$  input pins of the CS5464. The voltage channel is equipped with a 10x fixed-gain amplifier. The full-scale signal level that can be applied to the voltage channel is  $\pm 250\text{ mV}$ . If the input signal is a sine wave, the maximum RMS voltage at a gain 10x is:

$$\frac{250\text{mV}_P}{\sqrt{2}} \cong 176.78\text{mV}_{\text{RMS}}$$

which is approximately 70.7% of maximum peak voltage. The voltage channel is also equipped with a *Voltage Gain Register*, allowing for an additional programmable gain of up to 4x.

#### 5.1.2 Current Channel Inputs

The output of the current-sense resistor or transformer is connected to the  $I_{IN+}$  ( $I_{IN2+}$ ) and  $I_{IN-}$  ( $I_{IN2-}$ ) input pins of the CS5464. To accommodate different current-sensing elements, the current channel incorporates a programmable gain amplifier (PGA) with two programmable input gains. *Configuration Register* bit  $I_{gain}$  ( $I2_{gain}$ ) defines the two gain selections and corresponding maximum input signal level.

$I_{gain}$ , $I2_{gain}$	Maximum Input	Gain
0	$\pm 250\text{ mV}$	10x
1	$\pm 50\text{ mV}$	50x

**Table 1. Current Channel PGA Setting**

For example, if  $I_{gain}=0$  ( $I2_{gain}=0$ ), current channel 1(2) PGA gain is set to 10x. If the input signals are pure sinusoids with zero phase shift, the maximum peak differential signal on the current or voltage channel is  $\pm 250\text{ mV}_P$ . The input signal levels are approximately 70.7% of maximum peak voltage and produce a full-scale energy pulse registration equal to 50% of absolute maximum energy registration. This will be discussed further in See [Section 5.5 Energy Pulse Output](#) on page 18.

The *Current Gain Register* also facilitates an additional programmable gain of up to 4x. If an additional gain is

applied to the voltage and/or current channel, the maximum input range should be adjusted accordingly.

### 5.2 IIR Filters

The current and voltage channels are equipped with a 3<sup>rd</sup>-order IIR filter, that is used to compensate for the magnitude roll off of the low-pass decimation filter.

### 5.3 High-pass Filters

By removing the offset from either channel, no error component will be generated at DC when computing the active power. By removing the offset from both channels, no error component will be generated at DC when computing  $V_{\text{RMS}}$ ,  $I_{\text{RMS}}$ , and apparent power. *Operational Mode Register* bits  $V_{\text{HPF}}$ ,  $V_{\text{HPF}2}$ ,  $I_{\text{HPF}}$  and  $I_{\text{HPF}2}$  activate the HPF in the voltage and current channel, respectively. When a high-pass filter is active in only one channel, an all-pass filter (APF) is applied to the companion channel. The APF has an amplitude response that is flat within the channel bandwidth and is used for matching phase in systems where only one HPF is engaged.

$V_{\text{HPF}}(2)$	$I_{\text{HPF}}(2)$	Filter Configuration
0	0	All Filters Off on Channel 1(2)
0	1	HPF on Current Channel 1(2)
1	0	HPF on Voltage Channel 1(2)
1	1	HPF on Current & Voltage Channels 1(2)

**Table 2. High-pass Filter Configuration**

### 5.4 Performing Measurements

The CS5464 performs measurements of instantaneous voltage ( $V_n$ ) and current ( $I_n$ ), and calculates instantaneous power ( $P_n$ ) at an output word rate (OWR) of

$$\text{OWR} = \frac{(\text{MCLK}/K)}{1024}$$

where K is the value of the clock divider selected in the *Configuration Register* by bits  $K[3:0]$ . Note that a value of  $K[3:0] = 0000$  results in a clock divider setting of 16, rather than zero.

The RMS voltage ( $V_{\text{RMS}}$ ,  $V2_{\text{RMS}}$ ), RMS current ( $I_{\text{RMS}}$ ,  $I2_{\text{RMS}}$ ), and active power ( $P_{\text{active}}$ ,  $P2_{\text{active}}$ ) are computed using N instantaneous samples of  $V_n$ ,  $I_n$ , and  $P_n$  respectively, where N is the value in the *Cycle Count Register* and is referred to as a "computation cycle". The apparent power (S, S2) is the product of  $V_{\text{RMS}}$  and  $I_{\text{RMS}}$ . A computation cycle is derived from the master clock

(MCLK), with frequency: Under default conditions and

$$\text{Computation Cycle} = \frac{\text{OWR}}{N}$$

with  $K = 1$ ,  $N = 4000$ , and  $\text{MCLK} = 4.096 \text{ MHz}$  – the  $\text{OWR} = 4000$  and the  $\text{Computation Cycle} = 1 \text{ Hz}$ .

All measurements are available as a percentage of full scale. The format for *signed* registers is a two's complement, normalized value between -1 and +1. The format for *unsigned* registers is a normalized value between 0 and 1. A register value of

$$\frac{(2^{23} - 1)}{2^{23}} = 0.99999988$$

represents the maximum possible value.

At each instantaneous measurement, the  $\overline{\text{CRDY}}$  bit will be set in the *Status Register*, and the  $\overline{\text{INT}}$  pin will become active if the  $\overline{\text{CRDY}}$  bit is unmasked in the *Mask Register*. At the end of each computation cycle, the  $\overline{\text{DRDY}}$  bit will be set in the *Status Register*, and the  $\overline{\text{INT}}$  pin will become active if the  $\overline{\text{DRDY}}$  bit is unmasked in the *Mask Register*. When these bits are asserted, they must be cleared before they can be asserted again.

If the *Cycle Count Register* ( $N$ ) is set to 2, all output calculations are instantaneous, and  $\overline{\text{DRDY}}$ , like  $\overline{\text{CRDY}}$ , will indicate when instantaneous measurements are finished. The *Cycle Count Register* ( $N$ ) must be  $\geq 2$ .

Epsilon ( $\mathcal{E}$ ) is the ratio of the input line frequency ( $f_i$ ) to the sample frequency ( $f_s$ ) of the ADC.

$$\mathcal{E} = f_i / f_s$$

where  $f_s = \text{MCLK} / (K \times 1024)$ . With  $\text{MCLK} = 4.096 \text{ MHz}$  and clock divider  $K = 1$ ,  $f_s = 4000 \text{ Hz}$ . For the two most-common line frequencies, 50 Hz and 60 Hz

$$\mathcal{E} = 50 \text{ Hz} / 4000 \text{ Hz} = 0.0125$$

and

$$\mathcal{E} = 60 \text{ Hz} / 4000 \text{ Hz} = 0.015$$

respectively. Epsilon is used to set the gain of the 90° phase shift (IIR) filter for the average reactive power calculation.

## 5.5 Energy Pulse Output

The CS5464 provides three output pins for energy registration. By default,  $\overline{\text{E1}}$  is used to register active energy,  $\overline{\text{E3}}$  is used to register reactive energy, and  $\overline{\text{E2}}$  indicates

the sign of both active and reactive energy. (See [Figure 2. Timing Diagram for E1, E2, and E3](#) on page 13.)

The  $\overline{\text{E1}}$  pulse output is designed to indicate the Active Energy. The  $\overline{\text{E2}}$  pin can be used to register Apparent Energy, to indicate a tamper detection has occurred, or to indicate the sign of energy. Table 3 defines the pulse output mode, which is controlled by bit  $\text{E2MODE}[1:0]$  in the *Operational Mode Register*.

E2MODE1	E2MODE0	$\overline{\text{E2}}$ Output Mode
0	0	Sign of Energy
0	1	Apparent Energy
1	0	Tamper Indicator
1	1	Reserved

**Table 3.  $\overline{\text{E2}}$  Pin Configuration**

The  $\overline{\text{E3}}$  pin can be set to register Reactive Energy (default), PFMON, Voltage Channel Sign, or Apparent Energy. Table 4 defines the pulse output format, which is controlled by bits  $\text{E3MODE}[1:0]$  in the *Operational Mode Register*.

E3MODE1	E3MODE0	$\overline{\text{E3}}$ OutPut Mode
0	0	Reactive Energy
0	1	PFMON
1	0	Voltage Channel Sign
1	1	Apparent Energy

**Table 4.  $\overline{\text{E3}}$  Pin Configuration**

The pulse output frequencies of  $\overline{\text{E1}}$ ,  $\overline{\text{E2}}$ , and  $\overline{\text{E3}}$  are directly proportional to the power calculated from the input signals. The value contained in the *PulseRateE Register* is the ratio of the frequency of energy-output pulses to the number of samples, at full scale, which defines the average frequency for the output pulses. The pulse width,  $t_{pw}$  in [Figure 2](#), is an integer multiple of MCLK cycles approximately equal to:

$$t_{pw}(\text{sec}) \cong \frac{1}{(\text{MCLK}/K) / 1024}$$

If  $\text{MCLK} = 4.096 \text{ MHz}$  and  $K = 1$  then  $t_{pw} \cong 0.25 \text{ ms}$ .

### 5.5.1 Active Energy

The  $\overline{\text{E1}}$  pin produces active-low pulses with an output frequency proportional to the active power. The  $\overline{\text{E2}}$  pin is the energy direction indicator. Positive energy is represented by  $\overline{\text{E1}}$  pin falling while the  $\overline{\text{E2}}$  is high. Negative energy is represented by the  $\overline{\text{E1}}$  pin falling while the  $\overline{\text{E2}}$  is low. The  $\overline{\text{E1}}$  and  $\overline{\text{E2}}$  switching characteristics are

specified in [Figure 2. Timing Diagram for E1, E2, and E3](#) on page 13.

[Figure 6](#) illustrates the pulse output format with positive active energy and negative reactive energy.



**Figure 6. Active and Reactive energy pulse outputs**

The pulse output frequency of  $\overline{E1}$  is directly proportional to the active power calculated from the input signals. To calculate the output frequency of  $\overline{E1}$ , the following transfer function can be utilized:

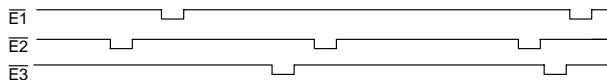
$$FREQ_P = \frac{VIN \times VGAIN \times IIN \times IGAIN \times PF \times PulseRate}{VREFIN^2}$$

$FREQ_P$  = Average frequency of active energy  $\overline{E1}$  pulses [Hz]  
 $VIN$  = rms voltage across  $VIN+$  and  $VIN-$  [V]  
 $VGAIN$  = Voltage channel gain  
 $IIN$  = rms voltage across  $IIN+$  and  $IIN-$  [V]  
 $IGAIN$  = Current channel gain  
 $PF$  = Power Factor  
 $PulseRate$  =  $PulseRateE \times (MCLK/K)/2048$  [Hz]  
 $VREFIN$  = Voltage at  $VREFIN$  pin [V]

With  $MCLK = 4.096$  MHz,  $PF = 1$ , and default settings, the pulses will have an average frequency equal to the frequency specified by  $PulseRateE$  when the input signals applied to the voltage and current channels cause full-scale readings in the instantaneous voltage and current registers. The maximum pulse frequency from the  $\overline{E1}$  pin is  $(MCLK/K)/2048$ .

### 5.5.2 Apparent Energy Mode

Pin  $\overline{E2}$  outputs apparent energy pulses when the *Operational Mode Register* bit  $E2MODE = 1$ . Pin  $\overline{E3}$  outputs apparent energy pulses when the *Operational Mode Register* bits  $E3MODE[1:0] = 3$  (11b). [Figure 7](#) illustrates the pulse output format with apparent energy on  $\overline{E2}$  ( $E2MODE = 1$  and  $E3MODE[1:0] = 0$ )



**Figure 7. Apparent energy pulse outputs**

The pulse output frequency of  $\overline{E2}$  (and/or  $\overline{E3}$ ) is directly proportional to the apparent power calculated from the input signals. Since apparent power is without reference to an impedance phase angle, the following transfer

function can be utilized to calculate the output frequency on  $\overline{E2}$  (and/or  $\overline{E3}$ ).

$$FREQ_S = \frac{VIN \times VGAIN \times IIN \times IGAIN \times PulseRate}{VREFIN^2}$$

$FREQ_S$  = Average frequency of apparent energy  $\overline{E2}$  and/or  $\overline{E3}$  pulses [Hz]  
 $VIN$  = rms voltage across  $VIN+$  and  $VIN-$  [V]  
 $VGAIN$  = Voltage channel gain  
 $IIN$  = rms voltage across  $IIN+$  and  $IIN-$  [V]  
 $IGAIN$  = Current channel gain  
 $PulseRate$  =  $PulseRateE \times (MCLK/K)/2048$  [Hz]  
 $VREFIN$  = Voltage at  $VREFIN$  pin [V]

With  $MCLK = 4.096$  MHz and default settings, the pulses will have an average frequency equal to the frequency specified by  $PulseRateE$  when the input signals applied to the voltage and current channels cause full-scale readings in the instantaneous voltage and current registers. The maximum pulse frequency from the  $\overline{E2}$  (and/or  $\overline{E3}$ ) pin is  $(MCLK/K)/2048$ . The  $\overline{E2}$  (and/or  $\overline{E3}$ ) pin outputs apparent energy, but has no energy direction indicator.

### 5.5.3 Reactive Energy Mode

Reactive energy pulses are output on pin  $\overline{E3}$  by setting bit  $E3MODE[1:0] = 0$  (default) in the *Operational Mode Register*. Positive reactive energy is registered by  $\overline{E3}$  falling when  $\overline{E2}$  is high. Negative reactive energy is registered by  $\overline{E3}$  falling when  $\overline{E2}$  is low. [Figure 6](#) on page 19 illustrates the pulse output format with negative reactive energy output on pin  $\overline{E3}$  and the sign of the energy on  $\overline{E2}$ . The  $\overline{E3}$  and  $\overline{E2}$  pulse output switching characteristics are specified in [Figure 2](#) on page 13.

The pulse output frequency of  $\overline{E3}$  is directly proportional to the reactive power calculated from the input signals. To calculate the output frequency on  $\overline{E3}$ , the following transfer function can be utilized:

$$FREQ_Q = \frac{VIN \times VGAIN \times IIN \times IGAIN \times PQ \times PulseRate}{VREFIN^2}$$

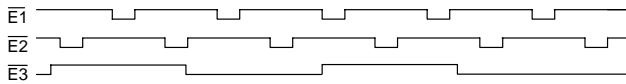
$FREQ_Q$  = Average frequency of reactive energy  $\overline{E3}$  pulses [Hz]  
 $VIN$  = rms voltage across  $VIN+$  and  $VIN-$  [V]  
 $VGAIN$  = Voltage channel gain  
 $IIN$  = rms voltage across  $IIN+$  and  $IIN-$  [V]  
 $IGAIN$  = Current channel gain  
 $PQ = \sqrt{1 - PF^2}$   
 $PulseRate$  =  $PulseRateE \times (MCLK/K)/2048$  [Hz]  
 $VREFIN$  = Voltage at  $VREFIN$  pin [V]

With  $MCLK = 4.096$  MHz,  $PF = 0$  and default settings, the pulses will have an average frequency equal to the frequency specified by  $PulseRateE$  when the input signals applied to the voltage and current channels cause full-scale readings in the instantaneous voltage and cur-

rent registers. The maximum pulse frequency from the E1 pin is  $(MCLK/K)/2048$ .

### 5.5.4 Voltage Channel Sign Mode

Setting bits E3MODE[1:0] = 2 (10b) in the *Operational Mode Register* outputs the sign of the voltage channel on pin E3. Figure 8 illustrates the output format with voltage channel sign on E3.

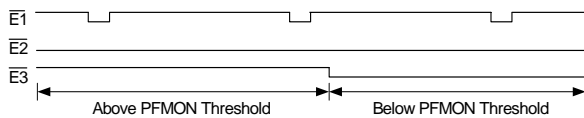


**Figure 8. Voltage Channel Sign Pulse outputs**

Output pin E3 is high when the line voltage is positive and pin E3 is low when the line voltage is negative.

### 5.5.5 PFMON Output Mode

Setting bit E3MODE[1:0] = 1 (01b) in the *Operational Mode Register* outputs the state of the PFMON comparator on pin E3. Figure 9 illustrates the output format with PFMON on E3.



**Figure 9. PFMON output to pin E3**

When PFMON is greater than the threshold, pin E3 is high and when PFMON is less than the threshold pin E3 is low.

### 5.5.6 Design Example

#### EXAMPLE #1:

The maximum rated levels for a power line meter are 250 V rms and 20 A rms. The required number of pulses-per-second on E1 is 100 pulses per second (100 Hz), when the levels on the power line are 220 V rms and 15 A rms.

With a 10x gain on the voltage and current channel the maximum input signal is 250 mV<sub>P</sub>. (See Section 5.1 *Analog Inputs* on page 17.) To prevent over-driving the channel inputs, the maximum rated rms input levels will register 0.6 in V<sub>RMS</sub> and I<sub>RMS</sub> by design. Therefore the voltage level at the channel inputs will be 150 mV rms when the maximum rated levels on the power lines are 250 V rms and 20 A rms.

Solving for *PulseRateE* using the transfer function:

$$\text{PulseRate} = \frac{\text{FREQ}_P \times \text{VREFIN}^2}{\text{VIN} \times \text{VGAIN} \times \text{IIN} \times \text{IGAIN} \times \text{PF}}$$

Therefore with PF = 1 and:

$$\text{VIN} = 220\text{V} \times ((150\text{mV}) / (250\text{V})) = 132\text{mV}$$

$$\text{IIN} = 15\text{A} \times ((150\text{mV}) / (20\text{A})) = 112.5\text{mV}$$

the pulse rate is:

$$\text{PulseRate} = \frac{100 \times 2.5^2}{0.132 \times 10 \times 0.1125 \times 10} = 420.8754\text{Hz}$$

and the *PulseRateE Register* is set to:

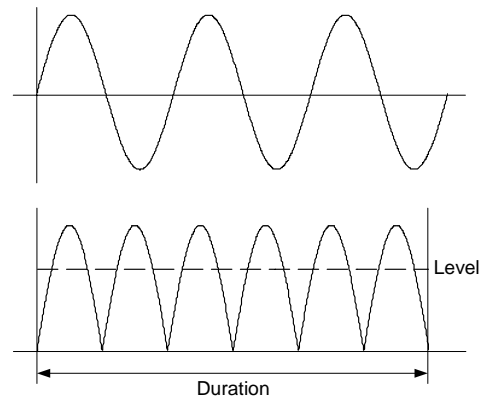
$$\text{PulseRateE} = \frac{\text{PulseRate}}{(MCLK/K)/2048} = 0.2104377$$

with MCLK = 4.096 MHz and K = 1.

### 5.6 Sag and Fault Detect Feature

Status bit VSAG (V2SAG) and IFAULT (I2FAULT) in the *Status Register*, indicates a sag occurred in the power line voltage (voltage 2) and current (current 2), respectively. For a sag condition to be identified, the absolute value of the instantaneous voltage or current must be less than the sag level for more than half of the sag duration (see Figure 10).

To activate voltage sag detection, a voltage sag level must be specified in the *Voltage Sag Level Register* (VSAG<sub>level</sub>, V2SAG<sub>level</sub>), and a voltage sag duration must be specified in the *Voltage Sag Duration Register* (VSAG<sub>duration</sub>, V2SAG<sub>duration</sub>). To activate current fault detection, a current sag level must be specified in the *Current Fault Level Register* (ISAG<sub>level</sub>, I2SAG<sub>level</sub>), and a current sag duration must be specified in the *Current Fault Duration Register* (ISAG<sub>duration</sub>, I2SAG<sub>duration</sub>). The voltage and current sag levels are specified as the average of the absolute instantaneous voltage and current, respectively. Voltage and current sag duration is specified in terms of ADC cycles.



**Figure 10. Sag and Fault Detect**

## 5.7 On-chip Temperature Sensor

The on-chip temperature sensor is designed to assist in characterizing the measurement element over a desired temperature range. Once a temperature characterization is performed, the temperature sensor can then be utilized to assist in compensating for temperature drift.

Temperature measurements are performed during continuous conversions and stored in the *Temperature Register*. The *Temperature Register* (T) default is Celsius scale (°C). The *Temperature Gain Register* (T<sub>gain</sub>) and *Temperature Offset Register* (T<sub>off</sub>) are constant values allowing for temperature scale conversions.

The temperature update rate is a function of the number of ADC samples. With MCLK = 4.096 MHz and K = 1 the update rate is:

$$\frac{2240 \text{ samples}}{(\text{MCLK}/K)/1024} = 0.56 \text{ sec}$$

The *Cycle Count Register* (N) must be set to a value greater than one. Status bit TUP in the *Status Register*, indicates when the *Temperature Register* is updated.

The *Temperature Offset Register* sets the zero-degree measurement. To improve temperature measurement accuracy, the zero-degree offset may need to be adjusted after the CS5464 is initialized. Temperature-offset calibration is achieved by adjusting the *Temperature Offset Register* (T<sub>off</sub>) by the differential temperature (ΔT) measured from a calibrated digital thermometer and the CS5464 temperature sensor. A one-degree adjustment to the *Temperature Register* (T) is achieved by adding  $2.737649 \times 10^{-4}$  to the *Temperature Offset Register* (T<sub>off</sub>). Therefore,

$$T_{\text{off}} = T_{\text{off}} + (\Delta T \times 2.737649 \cdot 10^{-4})$$

if T<sub>off</sub> = -0.094488 and ΔT = -2.0 (°C), then

$$T_{\text{off}} = (-0.094488 + (-2.0 \times 2.737649 \cdot 10^{-4})) = -0.09504$$

or 0xF3D5BB (2's compliment notation) is stored in the *Temperature Offset Register* (T<sub>off</sub>).

To convert the *Temperature Register* (T) from a Celsius scale (°C) to a Fahrenheit scale (°F) utilize the formula

$$^{\circ}\text{F} = \frac{9}{5}(^{\circ}\text{C} + 17.7778)$$

Applying the above relationship to the CS5461A temperature measurement algorithm

$$T(^{\circ}\text{F}) = \left(\frac{9}{5} \times T_{\text{gain}}\right) \left[ T(^{\circ}\text{C}) + (T_{\text{off}} + (17.7778 \times 2.737649 \cdot 10^{-4})) \right]$$

If T<sub>off</sub> = -0.09504 and T<sub>gain</sub> = 26.443 for a Celsius scale, then the modified values are T<sub>off</sub> = -0.09017 (0xF47550) and T<sub>gain</sub> = 47.6 (0x5F3333) for a Fahrenheit scale.

## 5.8 Voltage Reference

The CS5464 is specified for operation with a +2.5 V reference between the VREFIN and AGND pins. To utilize the on-chip 2.5 V reference, connect the VREFOUT pin to the VREFIN pin of the device. The VREFIN can be used to connect external filtering and/or references.

## 5.9 System Initialization

Upon powering up, the digital circuitry is held in reset until the analog voltage reaches 4.0 V. At that time, an eight-XIN-clock-period delay is enabled to allow the oscillator to stabilize. The CS5464 will then initialize.

A hardware reset is initiated when the  $\overline{\text{RESET}}$  pin is asserted with a minimum pulse width of 50 ns. The  $\overline{\text{RESET}}$  signal is asynchronous, with a Schmitt-trigger input. Once the  $\overline{\text{RESET}}$  pin is de-asserted, an eight-XIN-clock-period delay is enabled.

A software reset is initiated by writing the command 0x80. After a hardware or software reset, the internal registers (some of which drive output pins) will be reset to their default values. Status bit DRDY in the *Status Register*, indicates the CS5464 is in its *active* state and ready to receive commands.

## 5.10 Power-down States

The CS5464 has two power-down states, *Stand-by* and *Sleep*. In the stand-by state all circuitry except the voltage reference and crystal oscillator is turned off. To return the device to the active state, a power-up command is sent to the device.

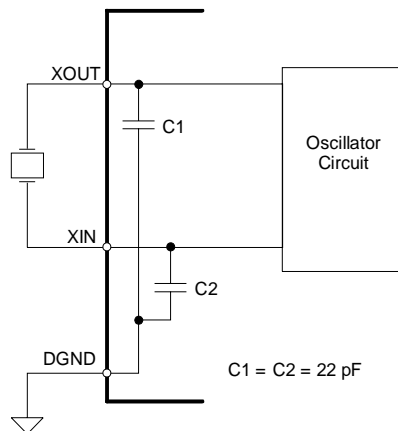
In Sleep state, all circuitry except the instruction decoder is turned off. When the power-up command is sent to the device, a system initialization is performed (See [Section 5.9 System Initialization](#) on page 21).

## 5.11 Oscillator Characteristics

XIN and XOUT are the input and output of an inverting amplifier configured as an on-chip oscillator, as shown in Figure 11. The oscillator circuit is designed to work

with a quartz crystal. To reduce circuit cost, two load capacitors C1 and C2 are integrated in the device, from XIN to DGND, and XOUT to DGND. PCB trace lengths should be minimized to reduce stray capacitance. To drive the device from an external clock source, XOUT should be left unconnected while XIN is driven by the external circuitry. There is an amplifier between XIN and the digital section which provides CMOS level signals. This amplifier works with sinusoidal inputs so there are no problems with slow edge times.

The CS5464 can be driven by an external oscillator ranging from 2.5 to 20 MHz, but the K divider value must be set such that the internal MCLK will run somewhere between 2.5 MHz and 5 MHz. The K divider value is set with the K[3:0] bits in the *Configuration Register*. As an example, if XIN = MCLK = 15 MHz, and K is set to 5, DCLK will equal 3 MHz, which is a valid value for DCLK.







**Figure 11. Oscillator Connection**

## 5.12 Event Handler

The  $\overline{\text{INT}}$  pin is used to indicate that an internal error or event has taken place in the CS5464. Writing a logic 1 to any bit in the *Mask Register* allows the corresponding bit in the *Status Register* to activate the  $\overline{\text{INT}}$  pin. The interrupt condition is cleared by writing a logic 1 to the bit that has been set in the *Status Register*.

The behavior of the  $\overline{\text{INT}}$  pin is controlled by the IMODE and IINV bits of the *Configuration Register*.

IMODE	IINV	$\overline{\text{INT}}$ Pin
0	0	Active-low Level 
0	1	Active-high Level 
1	0	Low Pulse 
1	1	High Pulse 

**Table 5. Interrupt Configuration**

If the interrupt output signal format is set for either falling or rising edge, the duration of the  $\overline{\text{INT}}$  pulse will be at least one DCLK cycle ( $\text{DCLK} = \text{MCLK}/\text{K}$ ).

### 5.12.1 Typical Interrupt Handler

The steps below show how interrupts can be handled.

#### INITIALIZATION:

- 1) All Status bits are cleared by writing 0xFFFFF to the Status Register.
- 2) The condition bits which will be used to generate interrupts are then set to logic 1 in the Mask Register.
- 3) Enable interrupts.

**INTERRUPT HANDLER ROUTINE:**

- 4) Read the Status Register.
- 5) Disable all interrupts.
- 6) Branch to the proper interrupt service routine.
- 7) Clear the Status Register by writing back the read value in step 4.
- 8) Re-enable interrupt
- 9) Return from interrupt service routine.

This handshaking procedure ensures that any new interrupts activated between steps 4 and 7 are not lost (cleared) by step 7.

### 5.13 Serial Port Overview

The CS5464 incorporates a serial port transmit and receive buffer with a command decoder that interprets one-byte (8-bit) commands as they are received. There are four types of commands: instructions, synchronizing, register writes, and register reads (See [Section 5.15 Commands](#) on page 24).

Instructions are one byte in length and will interrupt any instruction currently executing. Instructions do not affect register reads currently being transmitted.

Synchronizing commands are one byte in length and only affect the serial interface. Synchronizing commands do not affect operations currently in progress.

Register writes must be followed by three bytes of data. Register reads can return up to four bytes of data.

Commands and data are transferred most-significant bit (MSB) first. [Figure 1](#) on page 12, defines the serial port timing and required sequence necessary for writing to and reading from the serial port receive and transmit buffer, respectively. While reading data from the serial port, commands and data can be written simultaneously. Starting a new register read command while data is being read will terminate the current read in progress. This is acceptable if the remainder of the current read data is not needed. During data reads, the serial port requires input data. If a new command and data is not sent, SYNC0 or SYNC1 must be sent.

#### 5.13.1 Serial Port Interface

The serial port interface is a “4-wire” synchronous serial communications interface. The interface is enabled to start excepting SCLKs when  $\overline{CS}$  (Chip Select) is asserted (logic 0). SCLK (Serial bit-clock) is a Schmitt-trigger input that is used to strobe the data on SDI (Serial Data In) into the receive buffer and out of the transmit buffer onto SDO (Serial Data Out).

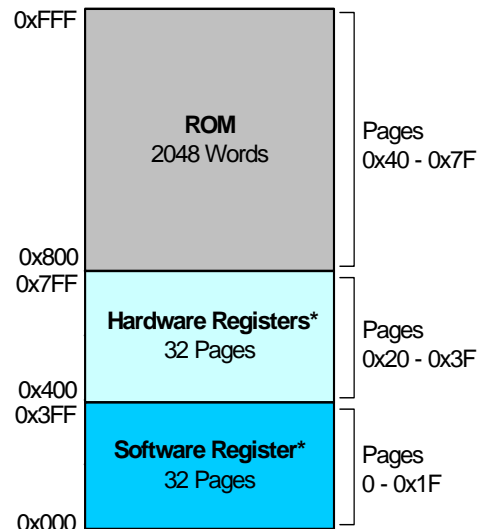
If the serial port interface becomes unsynchronized with respect to the SCLK input, any attempt to clock valid commands into the serial interface may result in unexpected operation. Therefore, the serial port interface must then be re-initialized by one of the following actions:

- Drive the  $\overline{CS}$  pin high, then low.
- Hardware Reset (drive  $\overline{RESET}$  pin low for at least 10  $\mu$ s).
- Issue the *Serial Port Initialization Sequence*, which is 3 (or more) SYNC1 command bytes (0xFF) followed by one SYNC0 command byte (0xFE).

If a re-synchronization is necessary, it is best to re-initialize the part either by hardware or software reset (command 0x80), as the state of the part may be unknown.

### 5.14 Register Paging

Read/write commands access one of the 32 registers within a specified page. By default, Page = 0. To access registers in another page, the *Page Register* (address 0x1F) must be written with the desired page number.



\* Accessed using register read/write commands.

**Figure 12. CS5464 Memory Map**

Example:

Reading register 6 in page 3.

1. Write 3 to page register with command and data:

0x7E 0x00 0x00 0x03

2. Read register 6 with command:

0x0C 0xFF 0xFF 0xFF

## 5.15 Commands

All commands are 8 bits in length. Any command byte value that is not listed in this section is invalid. Commands that write to registers must be followed by 3 bytes of data. Commands that read data can be chained with other commands (e.g., while reading data, a new command can be sent which can execute during the original read). All commands except register reads, register writes, and SYNC0 & SYNC1 will abort any currently executing commands.

### 5.15.1 Start Conversions

B7	B6	B5	B4	B3	B2	B1	B0
1	1	1	0	C3	0	0	0

Initiates acquiring measurements and calculating results. The device has two modes of acquisition.

C3	Modes of acquisition/measurement
0	= Perform a single computation cycle
1	= Perform continuous computation cycles

### 5.15.2 SYNC0 and SYNC1

B7	B6	B5	B4	B3	B2	B1	B0
1	1	1	1	1	1	1	SYNC

The serial port is resynchronized to byte boundaries by sending three or more consecutive SYNC1 commands followed by a SYNC0 command. The SYNC0 or SYNC1 commands can also be used as a NOP command.

SYNC	Designates calibration
0	= This command is the end of the serial port re-initialization sequence.
1	= This command is part of the serial port re-initialization sequence.

### 5.15.3 Power-down, Power-up, Halt and Software Reset

B7	B6	B5	B4	B3	B2	B1	B0
1	0	S1	S0	0	0	0	0

To conserve power the CS5464 has two power-down states. In stand-by state all circuitry, except the analog/digital clock generators, is turned off. In the sleep state all circuitry, except the digital clock generator and the command decoder, is turned off. Bringing the CS5464 out of sleep state requires more time than out of stand-by state, because of the extra time needed to re-start and re-stabilize the analog clock signal. If the device is powered-down, Power-Up/Halt will initiate a power on reset. If the part is already powered-on, all computations will be halted.

S[1:0]	Power-down state
00	= Software Reset
01	= Halt and enter sleep power saving state. This state requires a slow power-on time
10	= Power-up and Halt
11	= Halt and enter stand-by power saving state. This state allows quick power-on time



### 5.15.4 Register Read/Write

B7	B6	B5	B4	B3	B2	B1	B0
0	W/R	RA4	RA3	RA2	RA1	RA0	0

The Read/Write informs the command decoder that a register access is required. During a *read* operation, the addressed register is loaded into the device's output buffer and clocked out by SCLK. During a *write* operation, the data is clocked into the input buffer and transferred to the addressed register upon completion of the 24<sup>th</sup> SCLK.

$\overline{W/R}$       Write/Read control  
 0 = Read register  
 1 = Write register

RA[4:0]      Register address bits (bits 5 through 1) of the read/write command.

Page 0

Address	RA[4:0]	Name	Description
0	00000	Config	Configuration
1	00001	I	Instantaneous Current
2	00010	V	Instantaneous Voltage
3	00011	P	Instantaneous Power
4	00100	P <sub>Active</sub>	Average Active (Real) Power
5	00101	I <sub>RMS</sub>	RMS Current
6	00110	V <sub>RMS</sub>	RMS Voltage
7	00111	I2	Instantaneous Current 2
8	01000	V2	Instantaneous Voltage 2
9	01001	P2	Instantaneous Power 2
10	01010	P2 <sub>Active</sub>	Average Active (Real) Power 2
11	01011	I2 <sub>RMS</sub>	RMS Current 2
12	01100	V2 <sub>RMS</sub>	RMS Voltage 2
13	01101	Q <sub>Avg</sub>	Average Reactive Power
14	01110	Q	Instantaneous Reactive Power
15	01111	Status	Status (Write of '1' to status bit will clear the bit)
16	10000	Q2 <sub>Avg</sub>	Average Reactive Power 2
17	10001	Q2	Instantaneous Reactive Power 2
18	10010	I <sub>peak</sub>	Peak Current
19	10011	V <sub>peak</sub>	Peak Voltage
20	10100	S	Apparent Power
21	10101	PF	Power Factor
22	10110	I2 <sub>peak</sub>	Peak Current 2
23	10111	V2 <sub>peak</sub>	Peak Voltage 2
24	11000	S2	Apparent Power 2
25	11001	PF2	Power Factor 2
26	11010	Mask	Mask
27	11011	T	Temperature
28	11100	Ctrl	Control
29	11101	P <sub>pulse</sub>	Active Energy Pulse Output Accumulator
30	11110	S <sub>pulse</sub>	Apparent Energy Pulse Output Accumulator
31	11111	Q <sub>pulse</sub> / Page	Reactive Energy Pulse Output Accumulator (read only) and Page (write only)

Note: For proper operation, *do not* attempt to write to unspecified registers.

Page1

<u>Address</u>	<u>RA[4:0]</u>	<u>Name</u>	<u>Description</u>
0	00000	I <sub>dc</sub> off	Current DC offset
1	00001	I <sub>gn</sub>	Current Gain Calibration
2	00010	V <sub>dc</sub> off	Voltage DC offset
3	00011	V <sub>gn</sub>	Voltage Gain Calibration
4	00100	P <sub>off</sub>	Power Offset
5	00101	I <sub>ac</sub> off	Current AC (RMS) offset
6	00110	V <sub>ac</sub> off	Voltage AC (RMS) offset
7	00111	I <sub>2dc</sub> off	Current DC offset 2
8	01000	I <sub>2gn</sub>	Current Gain Calibration 2
9	01001	V <sub>2dc</sub> off	Voltage DC offset 2
10	01010	V <sub>2gn</sub>	Voltage Gain Calibration 2
11	01011	P <sub>2off</sub>	Power Offset 2
12	01100	I <sub>2ac</sub> off	Current AC (RMS) offset 2
13	01101	V <sub>2ac</sub> off	Voltage AC (RMS) offset 2
15	01111	PulseRateE	Sets the energy-to-frequency output pulse rate
16	10000	Mode	Operational Modes
17	10001	Epsilon	Epsilon
18	10010	Tamper <sub>level</sub>	Sets tamper threshold level
19	10011	Cycle Count	Number of conversions in one computation cycle (N)
20	10100	Q <sub>Trig</sub>	Reactive Power calculated from Power Triangle
21	10101	Q <sub>2Trig</sub>	Reactive Power calculated from Power Triangle 2
22	10110	T <sub>Gain</sub>	Temperature Sensor Gain
23	10111	T <sub>off</sub>	Temperature Sensor Offset
28	11100	SYS <sub>gain</sub>	System Gain

Page2

<u>Address</u>	<u>RA[4:0]</u>	<u>Name</u>	<u>Description</u>
0	00000	VSAG <sub>duration</sub>	VSAG Duration
1	00001	VSAG <sub>level</sub>	VSAG Level
4	00100	ISAG <sub>duration</sub>	ISAG Duration
5	00101	ISAG <sub>level</sub>	ISAG Level
8	01000	V2SAG <sub>duration</sub>	VSAG Duration 2
9	01001	V2SAG <sub>level</sub>	VSAG Level 2
12	01100	I2SAG <sub>duration</sub>	ISAG Duration 2
13	01101	I2SAG <sub>level</sub>	ISAG Level 2

Note: For proper operation, *do not* attempt to write to unspecified registers.

### 5.15.5 Calibration

B7	B6	B5	B4	B3	B2	B1	B0
1	0	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0

The CS5464 can perform system calibrations. Proper input signals must be applied to the current and voltage channel before performing a designated calibration.

CAL[5:4]\*      Designates calibration to be performed  
00 = Channel DC offset  
01 = Channel DC gain  
10 = Channel AC offset  
11 = Channel AC gain

CAL[3:0]\*      Designates channel to calibrate  
0001 = Current channel  
0010 = Voltage channel  
0100 = Current channel 2  
1000 = Voltage channel 2

\*By utilizing different combinations for CAL[3:0], multiple channels can be calibrated simultaneously, e.g. CAL[5:0] = 001111 commands the CS5464 to perform a DC offset calibration on all four channels. Values for CAL[5:0] not specified should not be used.

## 6. REGISTER DESCRIPTION

1. “Default” = bit status after power-on or reset
2. Any bit not labeled is Reserved. A zero should always be used when writing to one of these bits.

### 6.1 Page 0 Registers

#### 6.1.1 Configuration (Config) Register

Address: 0

<b>23</b>	<b>22</b>	<b>21</b>	<b>20</b>	<b>19</b>	<b>18</b>	<b>17</b>	<b>16</b>
PC[7]	PC[6]	PC[5]	PC[4]	PC[3]	PC[2]	PC[1]	PC[0]
<b>15</b>	<b>14</b>	<b>13</b>	<b>12</b>	<b>11</b>	<b>10</b>	<b>9</b>	<b>8</b>
EWA	-	-	IMODE	IINV	-	-	-
<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
-	-	-	iCPU	K[3]	K[2]	K[1]	K[0]

Default = 0x000001

**PC[7:0]** Phase compensation. Sets a delay in the voltage channel relative to the current channel 1. Default setting is 00000000 = 0.0215 degree phase delay at 60 Hz (when MCLK = 4.096 MHz).

**EWA** Allows the  $\overline{E1}$  and  $\overline{E2}$  pins to be configured as open-collector output pins.  
 0 = Normal outputs (default)  
 1 = Only the pull-down device of the  $\overline{E1}$  and  $\overline{E2}$  pins are active

**IMODE, IINV** Soft interrupt configuration bits. Select the desired pin behavior for indication of an interrupt.  
 00 = Active-low level (default)  
 01 = Active-high level  
 10 = Low pulse  
 11 = High pulse

**iCPU** Inverts the CPUCLK clock. In order to reduce the level of noise present when analog signals are sampled, the logic driven by CPUCLK should not be active during the sample edge.  
 0 = Normal operation (default)  
 1 = Minimize noise when CPUCLK is driving rising edge logic

**K[3:0]** Clock divider. A 4-bit binary number used to divide the value of MCLK to generate the internal clock DCLK. The internal clock frequency is  $DCLK = MCLK/K$ . The value of K can range between 1 and 16. Note that a value of “0000” will set K to 16 (not zero). K = 1 at reset.

### 6.1.2 Instantaneous Current (I, I2), Voltage (V, V2), and Power (P, P2) Registers

Address: 1 (I), 2 (V), 3 (P), 7 (I2), 8 (V2), 9 (P2)

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

I (I2) and V (V2) contain the instantaneous measured values for current and voltage, respectively. The instantaneous voltage (voltage 2) and current (current 2) samples are multiplied to obtain Instantaneous Power, P (P2). The value is represented in two's complement notation and in the range of  $-1.0 \leq I, V, P < 1.0$  ( $-1.0 \leq I2, V2, P2 < 1.0$ ), with the binary point to the right of the MSB.

### 6.1.3 Active (Real) Power ( $P_{Active}$ , $P2_{Active}$ ) Registers

Address: 4 ( $P_{Active}$ ), 10 ( $P2_{Active}$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The instantaneous power is averaged over each computation cycle (N conversions) to compute Active Power,  $P_{Active}$  ( $P2_{Active}$ ). The value will be within in the range of  $-1.0 \leq P_{Active} < 1.0$  ( $-1.0 \leq P2_{Active} < 1.0$ ). The value is represented in two's complement notation, with the binary point to the right of the MSB.

### 6.1.4 RMS Current ( $I_{RMS}$ , $I2_{RMS}$ ) & Voltage ( $V_{RMS}$ , $V2_{RMS}$ ) Registers

Address: 5 ( $I_{RMS}$ ), 6 ( $V_{RMS}$ ), 11 ( $I2_{RMS}$ ), 12 ( $V2_{RMS}$ )

MSB														LSB	
$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	$2^{-8}$	.....	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$	$2^{-24}$

$I_{RMS}$  ( $I2_{RMS}$ ) and  $V_{RMS}$  ( $V2_{RMS}$ ) contain the Root Mean Square (RMS) values of I (I2) and V (V2), calculated each computation cycle. The value is represented in unsigned binary notation and in the range of  $0.0 \leq I_{RMS}, V_{RMS} < 1.0$  ( $0.0 \leq I2_{RMS}, V2_{RMS} < 1.0$ ), with the binary point to the left of the MSB.

### 6.1.5 Instantaneous Reactive Power (Q, Q2) Registers

Address: 14 (Q), 17 (Q2)

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The Instantaneous Reactive Power (Q, Q2) is the product of the voltage (voltage 2) signal, shifted 90 degrees, and the current (current 2) signal. The value is represented in two's complement notation and in the range of  $-1.0 < Q < 1.0$  ( $1.0 < Q2 < 1.0$ ), with the binary point to the right of the MSB.

### 6.1.6 Average Reactive Power ( $Q_{Avg}$ , $Q2_{Avg}$ ) Registers

Address: 13 ( $Q_{Avg}$ ), 16 ( $Q2_{Avg}$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The Average Reactive Power ( $Q_{Avg}$ ,  $Q2_{Avg}$ ) is Q (Q2) averaged over N samples. The value is represented in two's complement notation and in the range of  $-1.0 < Q_{Avg} < 1.0$  ( $-1.0 < Q2_{Avg} < 1.0$ ), with the binary point to the right of the MSB.

### 6.1.7 Status (Status) and Mask (Mask) Register

Address: 15 (Status); 26 (Mask)

<b>23</b>	<b>22</b>	<b>21</b>	<b>20</b>	<b>19</b>	<b>18</b>	<b>17</b>	<b>16</b>
DRDY	I2OR	V2OR	CRDY	I2ROR	V2ROR	IOR	VOR
<b>15</b>	<b>14</b>	<b>13</b>	<b>12</b>	<b>11</b>	<b>10</b>	<b>9</b>	<b>8</b>
E2OR	IROR	VROR	EOR	IFAULT	VSAG	I2FAULT	V2SAG
<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
TUP	V2OD	I2OD	VOD	IOD	LSD	FUP	IC

Default = 0x800001 (Status Register), 0x000000 (Mask Register)

The Status Register indicates status within the chip. In normal operation, writing a '1' to a bit will cause the bit to reset. Writing a '0' to a bit will not change its current state.

The Mask Register is used to control the activation of the  $\overline{INT}$  pin. Placing a logic '1' in a Mask bit will allow the corresponding bit in the Status Register to activate the  $\overline{INT}$  pin when the status bit is asserted.

DRDY	Data Ready. During conversions, this bit will indicate the end of computation cycles. For calibrations, this bit indicates the end of a calibration sequence.
IOR (I2OR)	Current Out of Range. Set when the magnitude of the measured current value causes the I (I2) register to overflow.
VOR (V2OR)	Voltage Out of Range. Set when the magnitude of the measured voltage value causes the V (V2) register to overflow.
CRDY	Conversion Ready. Indicates a new conversion is ready. This will occur at the output word rate.
IROR (I2ROR)	RMS Current Out of Range. Set when the calculated RMS current value causes the $I_{RMS}$ ( $I2_{RMS}$ ) register to overflow.
VROR (V2ROR)	RMS Voltage Out of Range. Set when the calculated RMS voltage value causes the $V_{RMS}$ ( $V2_{RMS}$ ) register to overflow.
EOR (E2OR)	Energy Out of Range. Set when $P_{Active}$ ( $P2_{Active}$ ) overflows.
IFAULT (I2FAULT)	Indicates a current fault occurred in the power line current. If the absolute value of the instantaneous current is less than $ISAG_{level}$ ( $I2SAG_{level}$ ) for more than half of the $ISAG_{duration}$ ( $I2SAG_{duration}$ ), the IFAULT (I2FAULT) bit will be set.
VSAG (V2SAG)	Indicates a voltage sag occurred in the power line voltage. If the absolute value of the instantaneous voltage is less than $VSAG_{level}$ ( $V2SAG_{level}$ ) for more than half of the $VSAG_{duration}$ ( $V2SAG_{duration}$ ), the VSAG (V2SAG) bit will be set.
TUP	Temperature Updated. Indicates a temperature conversion is ready.
VOD (V2OD)	Modulator Oscillation Detected on the voltage (voltage 2) channel. Set when the modulator oscillates due to an input above full scale. The level at which the modulator oscillates is significantly higher than the voltage (voltage 2) channel's differential input voltage range.
IOD (I2OD)	Modulator Oscillation Detected on the current (current 2) channel. Set when the modulator oscillates due to an input above full scale. The level at which the modulator oscillates is significantly higher than the current (current 2) channel's differential input voltage range.

Note: The IOD (I2OD) and VOD (V2OD) bits may be 'falsely' triggered by very brief voltage

spikes from the power line. This event should not be confused with a DC overload situation at the inputs, when the IOD (I2OD) and VOD (V2OD) bits will re-assert themselves even after being cleared, multiple times.

- LSD** Low Supply Detect. Set when the voltage at the PFMON pin falls below the low-voltage threshold (PML0), with respect to AGND pin. For a given part, PML0 can be as low as 2.3 V. LSD bit cannot be permanently reset until the voltage at PFMON pin rises back above the high-voltage threshold (PMHI), which is typically 100 mV above the device's low-voltage threshold. PMHI will never be greater than 2.7 V.
- FUP** Epsilon Updated. Indicates an update to the epsilon value has been placed in the register.
- $\overline{IC}$**  Invalid Command. Normally logic 1. Set to logic 0 if the host interface is strobed with an 8-bit word that is not recognized as one of the valid commands (see See [Section 5.15 Commands](#) on page 24).

### 6.1.8 Peak Current ( $I_{peak}$ , $I2_{peak}$ ) and Peak Voltage ( $V_{peak}$ , $V2_{peak}$ ) Register

Address: 18 ( $I_{peak}$ ), 19 ( $V_{peak}$ ), 22 ( $I2_{peak}$ ), 23 ( $V2_{peak}$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The Peak Current ( $I_{peak}$ ,  $I2_{peak}$ ) and Peak Voltage ( $V_{peak}$ ,  $V2_{peak}$ ) registers contain the instantaneous current and voltage with the greatest magnitude detected during the last computation cycle. The value is represented in two's complement notation and in the range of  $-1.0 \leq I_{peak}$ ,  $V_{peak} < 1.0$  ( $-1.0 \leq I2_{peak}$ ,  $V2_{peak} < 1.0$ ), with the binary point to the right of the MSB.

### 6.1.9 Apparent Power ( $S$ , $S2$ ) Register

Address: 20 ( $S$ ), 24 ( $S2$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Apparent power  $S$  ( $S2$ ) is the product of the  $V_{RMS}$  and  $I_{RMS}$  ( $V2_{RMS}$  and  $I2_{RMS}$ ). The value is represented in unsigned notation and in the range of  $0 \leq S < 1.0$  ( $0 \leq S2 < 1.0$ ), with the binary point to the right of the MSB.

### 6.1.10 Power Factor ( $PF$ , $PF2$ ) Register

Address: 21, 25

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Power Factor is calculated by dividing the Active (Real) Power by Apparent Power. The value is represented in two's complement notation and in the range of  $-1.0 \leq PF < 1.0$  ( $-1.0 \leq PF2 < 1.0$ ), with the binary point to the right of the MSB.

### 6.1.11 Temperature (T) Register

Address: 27

MSB										LSB					
-(2 <sup>7</sup> )	2 <sup>6</sup>	2 <sup>5</sup>	2 <sup>4</sup>	2 <sup>3</sup>	2 <sup>2</sup>	2 <sup>1</sup>	2 <sup>0</sup>	.....	2 <sup>-10</sup>	2 <sup>-11</sup>	2 <sup>-12</sup>	2 <sup>-13</sup>	2 <sup>-14</sup>	2 <sup>-15</sup>	2 <sup>-16</sup>

T contains measurements from the on-chip temperature sensor. Measurements are performed during continuous conversions, with the default the Celsius scale (°C). The value is represented in two's complement notation and in the range of  $-128.0 \leq T < 128.0$ , with the binary point to the right of the eighth MSB.

### 6.1.12 Control (Ctrl) Register

Register Address: 28

23	22	21	20	19	18	17	16
PC2[7]	PC2[6]	PC2[5]	PC2[4]	PC2[3]	PC2[2]	PC2[1]	PC2[0]
15	14	13	12	11	10	9	8
-	-	-	I2gain	-	-	-	STOP
7	6	5	4	3	2	1	0
-	-	Igain	INTOD	-	NOCPU	NOOSC	-

Default = 0x000000

**PC2[7:0]** Phase compensation. Sets a delay in the voltage channel relative to current channel 2. Default setting is 00000000 = 0.0215 degree phase delay at 60 Hz (when MCLK = 4.096 MHz).

**Igain (I2gain)** Sets the gain of the current (current 2) PGA.  
 0 = Gain is 10 (default)  
 1 = Gain is 50

**STOP** Terminates the auto-boot sequence.  
 0 = Normal (default)  
 1 = Stop sequence

**INTOD** Converts  $\overline{\text{INT}}$  output pin to an open drain output.  
 0 = Normal (default)  
 1 = Open drain

**NOCPU** Saves power by disabling the CPUCLK pin.  
 0 = Normal (default)  
 1 = Disables CPUCLK

**NOOSC** Saves power by disabling the crystal oscillator.  
 0 = Normal (default)  
 1 = Disabling oscillator circuit



**6.1.13 Active Energy Pulse Output Accumulator ( $P_{pulse}$ ) Register**

Address: 29

<b>MSB</b>														<b>LSB</b>	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The Active Energy Pulse Output Accumulator ( $P_{pulse}$ ) contains the sum of the active power and is used to drive the pulse output. If a tamper condition is detected, this register is equal to  $P2_{Active}$ . The value is represented in two's complement notation and in the range of  $-1.0 \leq P_{pulse} < 1.0$ , with the binary point to the right of the MSB.

**6.1.14 Apparent Energy Pulse Output Accumulator ( $S_{pulse}$ ) Register**

Address: 30

<b>MSB</b>														<b>LSB</b>	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The Apparent Energy Pulse Output Accumulator ( $S_{pulse}$ ) contains the apparent power and is used to drive the pulse output. This result is updated after each computation cycle. If a tamper condition is detected, this register is equal to  $S2$ . The value is represented in two's complement notation and in the range of  $-1.0 \leq S_{pulse} < 1.0$ , with the binary point to the right of the MSB.

**6.1.15 Reactive Energy Pulse Output Accumulator ( $Q_{pulse}$ ) Register**

Address: 31 (read only)

<b>MSB</b>														<b>LSB</b>	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The Reactive Energy Pulse Output Accumulator ( $Q_{pulse}$ ) contains the sum of the reactive power and is used to drive the pulse output. If a tamper condition is detected, this register is equal to  $Q2_{Avg}$ . The value is represented in two's complement notation and in the range of  $-1.0 \leq Q_{pulse} < 1.0$ , with the binary point to the right of the MSB.

**6.1.16 Page Register**

Address: 31 (write only)

<b>MSB</b>						<b>LSB</b>
$2^6$	$2^5$	$2^4$	$2^3$	$2^2$	$2^1$	$2^0$

Default = 0x00

Determines which register page the serial port will access.

## 6.2 Page 1 Registers

### 6.2.1 Current DC Offset ( $I_{dcoff}$ , $I2_{dcoff}$ ) and Voltage DC Offset ( $V_{dcoff}$ , $V2_{dcoff}$ ) Registers

Address: 0 ( $I_{dcoff}$ ), 2 ( $V_{dcoff}$ ), 7 ( $I2_{dcoff}$ ), 9 ( $V2_{dcoff}$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Default = 0x000000

The DC Offset registers ( $I_{dcoff}$ ,  $V_{dcoff}$ ,  $I2_{dcoff}$ ,  $V2_{dcoff}$ ) are initialized to 0.0 on reset. When DC Offset calibration is performed, the register is updated with the DC offset measured over a computation cycle. DRDY will be set at the end of the calibration. This register may be read and stored for future system offset compensation. The value is represented in two's complement notation and in the range of  $-1.0 \leq I_{dcoff}$ ,  $V_{dcoff} < 1.0$  ( $-1.0 \leq I2_{dcoff}$ ,  $V2_{dcoff} < 1.0$ ), with the binary point to the right of the MSB. See [Section 7.1.2.1 DC Offset Calibration Sequence](#) on page 39 for more information.

### 6.2.2 Current Gain ( $I_{gn}$ , $I2_{gn}$ ) and Voltage Gain ( $V_{gn}$ , $V2_{gn}$ ) Registers

Address: 1 ( $I_{gn}$ ), 3 ( $V_{gn}$ ), 8 ( $I2_{gn}$ ), 10 ( $V2_{gn}$ )

MSB														LSB	
$2^1$	$2^0$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	.....	$2^{-16}$	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$

Default = 0x400000 = 1.000

The gain registers ( $I_{gn}$ ,  $V_{gn}$ ,  $I2_{gn}$ ,  $V2_{gn}$ ) are initialized to 1.0 on reset. When either a AC or DC Gain calibration is performed, the register is updated with the gain measured over a computation cycle. DRDY will be set at the end of the calibration. This register may be read and stored for future system gain compensation. The value is in the range  $0.0 \leq I_{gn}$ ,  $V_{gn} < 3.9999$  ( $0.0 \leq I2_{gn}$ ,  $V2_{gn} < 3.9999$ ), with the binary point to the right of the second MSB.

### 6.2.3 Power Offset ( $P_{off}$ , $P2_{off}$ ) Registers

Address: 4 ( $P_{off}$ ), 11 ( $P2_{off}$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Default = 0x000000

Power Offset ( $P_{off}$ ,  $P2_{off}$ ) is added to the instantaneous power being accumulated in the  $P_{active}$  ( $P2_{active}$ ) register, and can be used to offset contributions to the energy result that are caused by undesirable sources of energy that are inherent in the system. The value is represented in two's complement notation and in the range of  $-1.0 \leq P_{off} < 1.0$  ( $-1.0 \leq P2_{off} < 1.0$ ), with the binary point to the right of the MSB.

### 6.2.4 Current AC Offset ( $I_{acoff}$ , $I2_{acoff}$ ) and Voltage AC Offset ( $V_{acoff}$ , $V2_{acoff}$ ) Registers

Address: 5 ( $I_{acoff}$ ), 6 ( $V_{acoff}$ ), 12 ( $I2_{acoff}$ ), 13 ( $V2_{acoff}$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Default = 0x000000

The AC Offset Registers ( $V_{acoff}$ ,  $I_{acoff}$ ,  $V2_{acoff}$ ,  $I2_{acoff}$ ) are initialized to zero on reset, allowing for uncalibrated normal operation. AC Offset Calibration updates these registers. This sequence lasts approximately  $(6N + 30)$  ADC cycles (where N is the value of the *Cycle Count Register*). DRDY will be asserted at the end of the calibration.

These values may be read and stored for future system AC offset compensation. The value is represented in two's complement notation in the range of  $-1.0 \leq V_{acoff}, I_{acoff} < 1.0$  ( $-1.0 \leq V2_{acoff}, I2_{acoff} < 1.0$ ), with the binary point to the right of the MSB.

### 6.2.5 PulseRateE Register

Address: 15

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Default = 0x800000 = 1.00 (2 kHz @ 4.096 MHz MCLK)

*PulseRateE* sets the frequency of  $\overline{E1}$ ,  $\overline{E2}$ , &  $\overline{E3}$  pulses.  $\overline{E1}$ ,  $\overline{E2}$ ,  $\overline{E3}$  frequency = (MCLK x PulseRateE) / 2048 at full scale. For a 4 khz sample rate, the maximum pulse rate is 2 khz. The value is represented in two's complement notation and in the range is  $-1.0 \leq \text{PulseRateE} < 1.0$ , with the binary point to the right of the MSB. Negative values have the same effect as positive. See [Section 5.5 Energy Pulse Output](#) on page 18 for more information.

### 6.2.6 Operational Mode (Mode) Register

Address: 16

23	22	21	20	19	18	17	16
TAMPER	-	-	-	-	-	-	-
15	14	13	12	11	10	9	8
-	-	-	TOFF	-	E2MODE[1]	E2MODE[0]	VHPF2
7	6	5	4	3	2	1	0
IHPF2	VHPF	IHPF	-	E3MODE[1]	E3MODE[0]	POS	AFC

Default = 0x000000

**TAMPER** Indicates when the meter has been tampered with.  
 0 = Normal operation. Energy is registered using P. (default)  
 1 = Tamper condition has been detected. Energy is registered using P2.

**TOFF** Tamper Detection Off  
 0 = Enables tamper detection. (default)  
 1 = Disables tamper detection.

**E2MODE[1:0]** E2 Output Mode  
 00 = Sign of Active Power (default)  
 01 = Apparent Power  
 10 = Tamper Detect  
 11 = Reserved

**VHPF2:IHPF2** High-pass Filter Enable  
 00 = High-pass filter disabled on voltage channel 2 & current channel 2 (default)  
 01 = High-pass filter enabled on current channel 2 with all-pass filter on voltage channel 2  
 10 = High-pass filter enabled on voltage channel 2 with all-pass filter on current channel 2  
 11 = High-pass filter enabled on voltage channel 2 & current channel 2

**VHPF:IHPF** High-pass Filter Enable  
 00 = High-pass filter disabled on voltage channel 1 & current channel 1 (default)  
 01 = High-pass filter enabled on current channel 1 with all-pass filter on voltage channel 1  
 10 = High-pass filter enabled on voltage channel 1 with all-pass filter on current channel 1  
 11 = High-pass filter enabled on voltage channel 1 & current channel 1

- E3MODE1:0    E3 Output Mode  
 00 = Reactive Power (default)  
 01 = PFMON  
 10 = Voltage sign  
 11 = Apparent Power
- POS            Positive Energy Only. Negative energy pulses on E1 are suppressed. However, negative P register results will NOT be suppressed.
- AFC            Enables automatic line frequency measurement and sets the frequency of the local sine/cosine generator used in fundamental/harmonic measurements. When AFC is enabled, the Epsilon register will be updated periodically.

### 6.2.7 Epsilon ( $\epsilon$ ) Register

Address: 17

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Default = 0x01999A = 0.0125 sec

Epsilon ( $\epsilon$ ) is the ratio of the input line frequency to the sample frequency of the ADC (See [Section 5.4 Performing Measurements](#) on page 17). Epsilon is either written to the register, or measured during conversions. The value is represented in two's complement notation and in the range of  $-1.0 \leq \epsilon < 1.0$ , with the binary point to the right of the MSB. Negative values have no significance.

### 6.2.8 Tamper Threshold ( $Tamper_{level}$ ) Register

Address: 18

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Default = 828F5C = 2%

Tamper Threshold ( $Tamper_{level}$ ) sets the level at which the two active powers,  $P_{Active}$  or  $P2_{Active}$ , can differ before a tamper condition is detected. When this threshold is reached the CS5464 will use the higher of the two power calculation in the pulse out accumulation registers. The value is represented in two's complement notation and in the range of  $-1.0 \leq Tamper_{level} < 1.0$ , with the binary point to the right of the MSB.

### 6.2.9 Cycle Count Register

Address: 19

MSB														LSB	
$2^{23}$	$2^{22}$	$2^{21}$	$2^{20}$	$2^{19}$	$2^{18}$	$2^{17}$	$2^{16}$	.....	$2^6$	$2^5$	$2^4$	$2^3$	$2^2$	$2^1$	$2^0$

Default = 0x000FA0 = 4000

Cycle Count, denoted as N, determines the length of one *computation cycle*. During continuous conversions, the computation cycle frequency is  $(MCLK/K)/(1024*N)$ . A second computational cycle period occurs when  $MCLK = 4.096$  MHz,  $K = 1$ , and  $N = 4000$ . The Cycle Count register must be  $\geq 2$ .

**6.2.10 Reactive Power ( $Q_{Trig}$ ,  $Q2_{Trig}$ ) Registers**

 Address: 20 ( $Q_{Trig}$ ), 21 ( $Q2_{Trig}$ )

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

The Reactive Power ( $Q_{Trig}$ ,  $Q2_{Trig}$ ) is calculated using trigonometric identities. (See [Section 4.3 Power Measurements](#) on page 15). The value is represented in unsigned notation and in the range of  $0 \leq Q_{Trig} < 1.0$  ( $0 \leq Q2_{Trig} < 1.0$ ), with the binary point to the right of the MSB.

**6.2.11 Temperature Gain ( $T_{Gain}$ ) Register**

Address: 2

MSB														LSB	
$2^6$	$2^5$	$2^4$	$2^3$	$2^2$	$2^1$	$2^0$	$2^{-1}$	.....	$2^{-11}$	$2^{-12}$	$2^{-13}$	$2^{-14}$	$2^{-15}$	$2^{-16}$	$2^{-17}$

Default = 0x34E2E7 = 26.443169117

Temperature gain ( $T_{Gain}$ ) is utilized to convert from one temperature scale to another. The Celsius scale ( $^{\circ}\text{C}$ ) is the default. Values will be within in the range of  $0 \leq T_{Gain} < 128$ . The value is represented in unsigned notation, with the binary point to the right of bit 7th MSB.

**6.2.12 Temperature Offset ( $T_{off}$ ) Register**

Address: 3

MSB														LSB	
$-(2^0)$	$2^{-1}$	$2^{-2}$	$2^{-3}$	$2^{-4}$	$2^{-5}$	$2^{-6}$	$2^{-7}$	.....	$2^{-17}$	$2^{-18}$	$2^{-19}$	$2^{-20}$	$2^{-21}$	$2^{-22}$	$2^{-23}$

Default = 0xF38701 = -0.0974425

Temperature offset ( $T_{off}$ ) is used to remove the temperature channel's offset at the zero-degree reading. Values are represented in two's complement notation and in the range of  $-1.0 \leq T_{off} < 1.0$ , with the binary point to the right of the MSB.

## 6.3 Page 2 Registers

### 6.3.1 Voltage Sag Duration (VSAG<sub>duration</sub>, V2SAG<sub>duration</sub>) Registers

Address: 0 (VSAG<sub>duration</sub>), 8 (V2SAG<sub>duration</sub>)

MSB								LSB							
0	2 <sup>22</sup>	2 <sup>21</sup>	2 <sup>20</sup>	2 <sup>19</sup>	2 <sup>18</sup>	2 <sup>17</sup>	2 <sup>16</sup>	.....	2 <sup>6</sup>	2 <sup>5</sup>	2 <sup>4</sup>	2 <sup>3</sup>	2 <sup>2</sup>	2 <sup>1</sup>	2 <sup>0</sup>

Default = 0x000000

Voltage Sag Duration (VSAG<sub>duration</sub>, V2SAG<sub>duration</sub>) defines the number of instantaneous measurements utilized to determine a sag event. Setting these register to zero will disable this feature. The value is represented in unsigned notation. See [Section 5.6 Sag and Fault Detect Feature](#) on page 20

### 6.3.2 Current Fault Duration (ISAG<sub>duration</sub>, I2SAG<sub>duration</sub>) Registers

Address: 4 (ISAG<sub>duration</sub>), 12 (I2SAG<sub>duration</sub>)

MSB								LSB							
0	2 <sup>22</sup>	2 <sup>21</sup>	2 <sup>20</sup>	2 <sup>19</sup>	2 <sup>18</sup>	2 <sup>17</sup>	2 <sup>16</sup>	.....	2 <sup>6</sup>	2 <sup>5</sup>	2 <sup>4</sup>	2 <sup>3</sup>	2 <sup>2</sup>	2 <sup>1</sup>	2 <sup>0</sup>

Default = 0x000000

Current Fault Duration (ISAG<sub>duration</sub>, I2SAG<sub>duration</sub>) defines the number of instantaneous measurements utilized to determine a sag event. Setting these register to zero will disable this feature. The value is represented in unsigned notation. See [Section 5.6 Sag and Fault Detect Feature](#) on page 20.

### 6.3.3 Voltage Sag Level (VSAG<sub>level</sub>, V2SAG<sub>level</sub>) Registers

Address: 1 (VSAG<sub>level</sub>), 9 (V2SAG<sub>level</sub>)

MSB								LSB							
2 <sup>-1</sup>	2 <sup>-2</sup>	2 <sup>-3</sup>	2 <sup>-4</sup>	2 <sup>-5</sup>	2 <sup>-6</sup>	2 <sup>-7</sup>	2 <sup>-8</sup>	.....	2 <sup>-18</sup>	2 <sup>-19</sup>	2 <sup>-20</sup>	2 <sup>-21</sup>	2 <sup>-22</sup>	2 <sup>-23</sup>	2 <sup>-24</sup>

Default = 0x000000

Voltage Sag Level (VSAG<sub>level</sub>, V2SAG<sub>level</sub>) defines the voltage level that the magnitude of input samples, averaged over the sag duration, must fall below in order to register a sag condition. These value are represented in unsigned notation and in the range of  $0 \leq \text{VSAG}_{\text{level}} < 1.0$  ( $0 \leq \text{V2SAG}_{\text{level}} < 1.0$ ), with the binary point to the left of the MSB. See [Section 5.6 Sag and Fault Detect Feature](#) on page 20.

### 6.3.4 Current Fault Level (ISAG<sub>level</sub>, I2SAG<sub>level</sub>) Registers

Address: 5 (ISAG<sub>level</sub>), 13 (I2SAG<sub>level</sub>)

MSB								LSB							
2 <sup>-1</sup>	2 <sup>-2</sup>	2 <sup>-3</sup>	2 <sup>-4</sup>	2 <sup>-5</sup>	2 <sup>-6</sup>	2 <sup>-7</sup>	2 <sup>-8</sup>	.....	2 <sup>-18</sup>	2 <sup>-19</sup>	2 <sup>-20</sup>	2 <sup>-21</sup>	2 <sup>-22</sup>	2 <sup>-23</sup>	2 <sup>-24</sup>

Default = 0x000000

Current Fault Level (ISAG<sub>level</sub>, I2SAG<sub>level</sub>) defines the voltage level that the magnitude of input samples, averaged over the fault duration, must fall below in order to register a fault condition. These value are represented in unsigned notation and in the range of  $0 \leq \text{ISAG}_{\text{level}} < 1.0$  ( $0 \leq \text{I2SAG}_{\text{level}} < 1.0$ ), with the binary point to the left of the MSB. See [Section 5.6 Sag and Fault Detect Feature](#) on page 20.

## 7. SYSTEM CALIBRATION

### 7.1 Channel Offset and Gain Calibration

The CS5464 provides digital DC offset and gain compensation that can be applied to the instantaneous voltage and current measurements, and AC offset compensation to the voltage and current RMS calculations.

Since the voltage and current channels have independent offset and gain registers, system offset and/or gain can be performed on either channel without the calibration results from one channel affecting the other.

The computational flow of the calibration sequences are illustrated in Figure 13. The flow applies to both the voltage channel and current channel.

#### 7.1.1 Calibration Sequence

The CS5464 must be operating in its active state and ready to accept valid commands. Refer to 5.15 *Commands* on page 24. The calibration algorithms are dependent on the value N in the *Cycle Count Register* (see Figure 13). Upon completion, the results of the calibration are available in their corresponding register. The DRDY bit in the *Status Register* will be set. If the DRDY bit is to be output on the INT pin, then DRDY bit in the Mask Register must be set. The initial values in the AC gain and offset registers do affect the results of the calibration results.

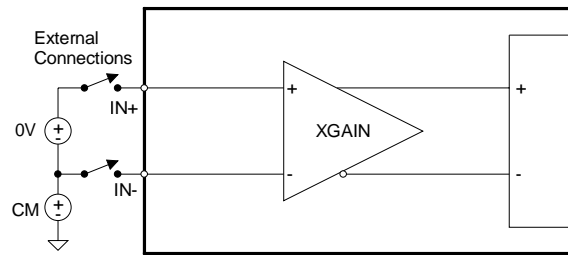
##### 7.1.1.1 Duration of Calibration Sequence

The value of the *Cycle Count Register* (N) determines the number of conversions performed by the CS5464 during a given calibration sequence. For DC offset and gain calibrations, the calibration sequence takes at least

$N + 30$  conversion cycles to complete. For AC offset calibrations, the sequence takes at least  $6N + 30$  ADC cycles to complete, (about 6 computation cycles). As N is increased, the accuracy of calibration results will increase.

#### 7.1.2 Offset Calibration Sequence

For DC and AC offset calibrations, the  $V_{IN\pm}$  ( $V2IN\pm$ ) pins of the voltage and  $I_{IN\pm}$  ( $I2IN\pm$ ) pins of the current channels should be connected to their ground reference level. (see Figure 14.)

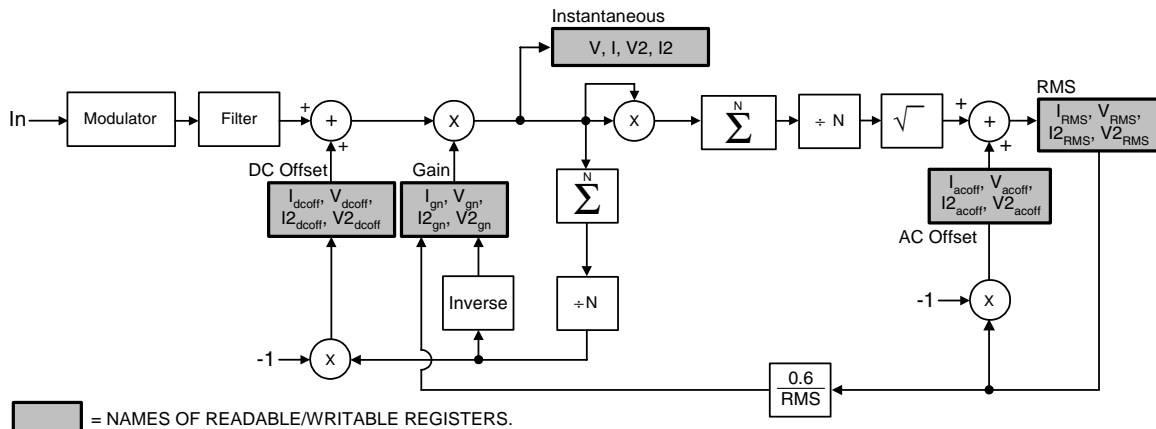


**Figure 14. System Calibration of Offset**

The AC offset registers must be set to the default (0x000000).

##### 7.1.2.1 DC Offset Calibration Sequence

Channel gain should be set to 1.0 when performing DC offset calibration. Initiate a DC offset calibration. The DC offset registers are updated with the negative of the average of the instantaneous samples collected over a computational cycle. Upon completion of the DC offset calibration the DC offset is stored in the corresponding DC offset register. The DC offset value will be added to



**Figure 13. Calibration Data Flow**

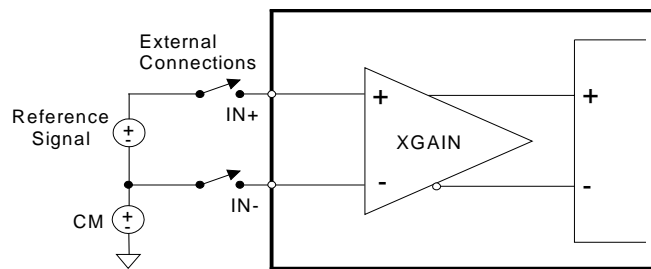
each instantaneous measurement to nullify the DC component present in the system during conversion commands.

### 7.1.2.2 AC Offset Calibration Sequence

Corresponding offset registers  $I_{acoff}$  ( $I2_{acoff}$ ) and/or  $V_{acoff}$  ( $V2_{acoff}$ ) should be cleared prior to initiating AC offset calibrations. Initiate an AC offset calibration. The AC offset registers are updated with an offset value that reflects the RMS output level. Upon completion of the AC offset calibration the AC offset is stored in the corresponding AC offset register. The AC offset register value is subtracted from each successive  $V_{RMS}$  and  $I_{RMS}$  calculation.

### 7.1.3 Gain Calibration Sequence

When performing gain calibrations, a reference signal should be applied to the  $VIN\pm$  ( $V2IN\pm$ ) pins of the voltage and  $IIN\pm$  ( $I2IN\pm$ ) pins of the current channels that represents the desired maximum signal level. Figure 15 shows the basic setup for gain calibration.



**Figure 15. System Calibration of Gain.**

For gain calibrations, there is an absolute limit on the RMS voltage levels that are selected for the gain calibration input signals. The maximum value that the gain registers can attain is 4. Therefore, if the signal level of the applied input is low enough that it causes the CS5464 to attempt to set either gain register higher than 4, the gain calibration result will be invalid and all CS5464 results obtained while performing measurements will be invalid.

If the channel gain registers are initially set to a gain other than 1.0, AC gain calibration should be used.

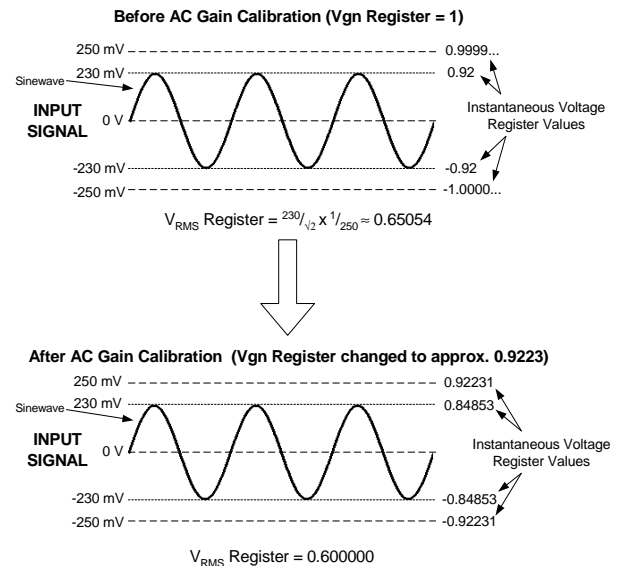
#### 7.1.3.1 AC Gain Calibration Sequence

The corresponding gain register should be set to 1.0, unless a different initial gain value is desired. Initiate an AC gain calibration. The AC gain calibration algorithm computes the RMS value of the reference signal applied to the channel inputs. The RMS register value is then divided into 0.6 and the quotient is stored in the corresponding gain register. Each instantaneous

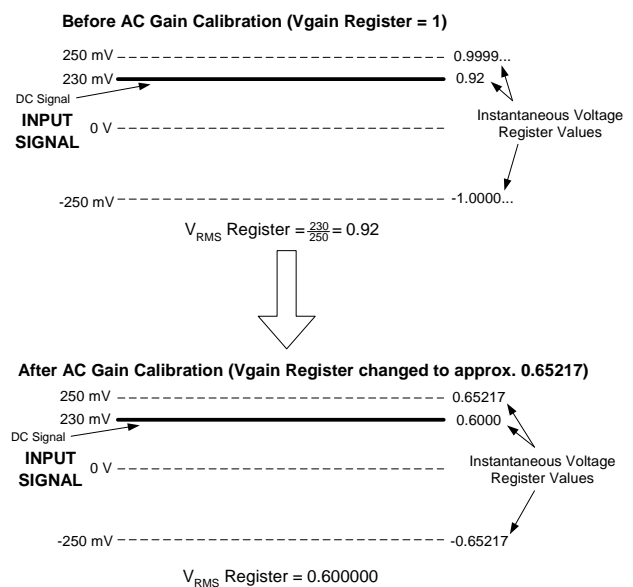
measurement will be multiplied by its corresponding AC gain value.

A typical rms calibration value which allows for reasonable over-range margin would be 0.6 or 60% of the voltage and current channel's maximum input voltage level.

Two examples of AC gain calibration and the updated digital output codes of the channel's instantaneous data registers are shown in Figure 16 and 17. Figure 17



**Figure 16. Example of AC Gain Calibration**



**Figure 17. Example of AC Gain Calibration**



shows that a positive (or negative) DC-level signal can be used even though an AC gain calibration is being executed.

However, an AC signal cannot be used for DC gain calibration.

### 7.1.3.2 DC Gain Calibration Sequence

Initiate a DC gain calibration. The corresponding gain register is restored to default (1.0). The DC gain calibration averages the channel's instantaneous measurements over one computation cycle (N samples). The average is then divided into 1.0 and the quotient is stored in the corresponding gain register

After the DC gain calibration, the instantaneous register will read at full-scale whenever the DC level of the input signal is equal to the level of the DC calibration signal applied to the inputs during the DC gain calibration. The HPF option should not be enabled if DC gain calibration is utilized.

### 7.1.4 Order of Calibration Sequences

1. If the HPF option is enabled, any DC component that may be present in the selected signal path will be removed and a DC offset calibration is not required. However, if the HPF option is disabled the DC offset calibration sequence should be performed.

When using high-pass filters, it is recommended that the DC Offset register for the corresponding channel be set to zero. When performing DC offset calibration, the corresponding gain channel should be set to one.

2. If there is an AC offset in the  $V_{RMS}$  or  $I_{RMS}$  calculation, the AC offset calibration sequence should be performed.
3. Perform the gain calibration sequence.
4. Finally, if an AC offset calibration was performed (step 2), the AC offset may need to be adjusted to compensate for the change in gain (step 3). This can be accomplished by restoring zero to the AC offset register and then perform an AC offset calibration sequence. The adjustment could also be done by

multiplying the AC offset register value that was calculated in step 2 by the gain calculated in step 3 and updating the AC offset register with the product.

## 7.2 Phase Compensation

The CS5464 is equipped with phase compensation to cancel out phase shifts introduced by the measurement element. Phase Compensation is set by bits PC[7:0] (for channel 1) in the *Configuration Register* and bits PC2[7:0] (for channel 2) in the *Control Register*

The default value of PC[7:0] (PC2[7:0]) is zero. With MCLK = 4.096 MHz and K = 1, the phase compensation has a range of  $\pm 5.4$  degrees when the input signals are 60 Hz. Under these conditions, each step of the phase compensation register (value of one LSB) is approximately 0.04 degrees. For values of MCLK other than 4.096 MHz, the range and step size should be scaled by  $4.096 \text{ MHz}/(\text{MCLK}/K)$ . For power line frequencies other than 60Hz, the values of the range and step size of the PC[7:0] (PC2[7:0]) bits can be determined by converting the above values from angular measurement into the time domain (seconds), and then computing the new range and step size (in degrees) with respect to the new line frequency. To calculate the phase shift induced between the voltage and the current channel use the equation:

$$\text{Phase} = \frac{\text{Freq} \times 360^\circ \times \text{PC}[7:0]}{(\text{MCLK}/K)/8}$$

Freq = Line Frequency [Hz]

PC[7:0] = 2's Complement number in the range of  $-128 \leq \text{PC}[7:0] < 127$

## 7.3 Active Power Offset

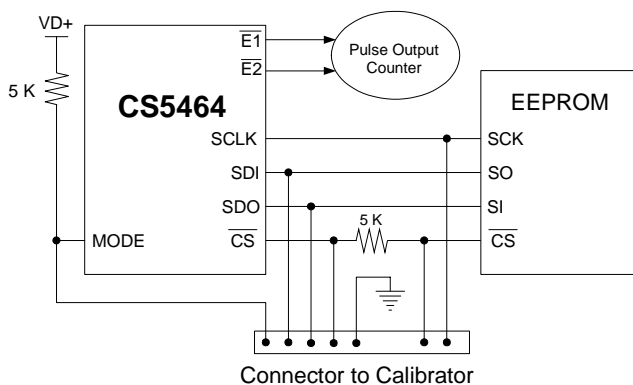
The *Power Offset Register* can be used to offset system power sources that may be resident in the system, but do not originate from the power line signal. These sources of extra energy in the system contribute undesirable and false offsets to the power and energy measurement results. After determining the amount of stray power, the Power Offset Register can be set to cancel the effects of this unwanted energy.

## 8. AUTO-BOOT MODE USING E<sup>2</sup>PROM

When the CS5464 MODE pin is asserted (logic 1), the CS5464 *auto-boot mode* is enabled. In auto-boot mode, the CS5464 downloads the required commands and register data from an external serial E<sup>2</sup>PROM, allowing the CS5464 to begin performing energy measurements.

### 8.1 Auto-boot Configuration

A typical auto-boot serial connection between the CS5464 and a E<sup>2</sup>PROM is illustrated in Figure 18. In auto-boot mode, the CS5464's CS and SCLK are configured as outputs. The CS5464 asserts CS (logic 0), provides a clock on SCLK, and sends a read command to the E<sup>2</sup>PROM on SDO. The CS5464 reads the user-specified commands and register data presented on the SDI pin. The E<sup>2</sup>PROM's programmed data is utilized by the CS5464 to change the designated registers' default values and begin registering energy.



**Figure 18. Typical Interface of E<sup>2</sup>PROM to CS5464**

Figure 18 also shows the external connections that would be made to a calibrator device, such as a PC or custom calibration board. When the metering system is installed, the calibrator would be used to control calibration and/or to program user-specified commands and calibration values into the E<sup>2</sup>PROM. The user-specified commands/data will determine the CS5464's exact operation, when the auto-boot initialization sequence is running. Any of the valid commands can be used.

### 8.2 Auto-boot Data for E<sup>2</sup>PROM

Below is an example code set for an auto-boot sequence. This code is written into the E<sup>2</sup>PROM by the user. The serial data for such a sequence is shown below in single-byte hexadecimal notation:

```

-7E 00 00 01
  Change to page 1.
-60 00 01 E0
  Write Operation Mode Register, turn high-pass
  filters on.
-42 7F C4 A9
  Write value of 0x7FC4A9 to Current Gain
  Register.
-46 FF B2 53
  Write value of 0xFFB253 to Voltage Gain
  Register.
-50 7F C4 A9
  Write value of 0x7FC4A9 to Current 2 Gain
  Register.
-54 FF B2 53
  Write value of 0xFFB253 to Voltage 2 Gain
  Register.
-7E 00 00 00
  Change to page 0.
-74 00 00 04
  Unmask bit #2 (LSD) in the Mask Register.
-E8
  Start continuous conversions
-78 00 01 00
  Write STOP bit to Control Register, to terminate
  auto-boot initialization sequence.

```

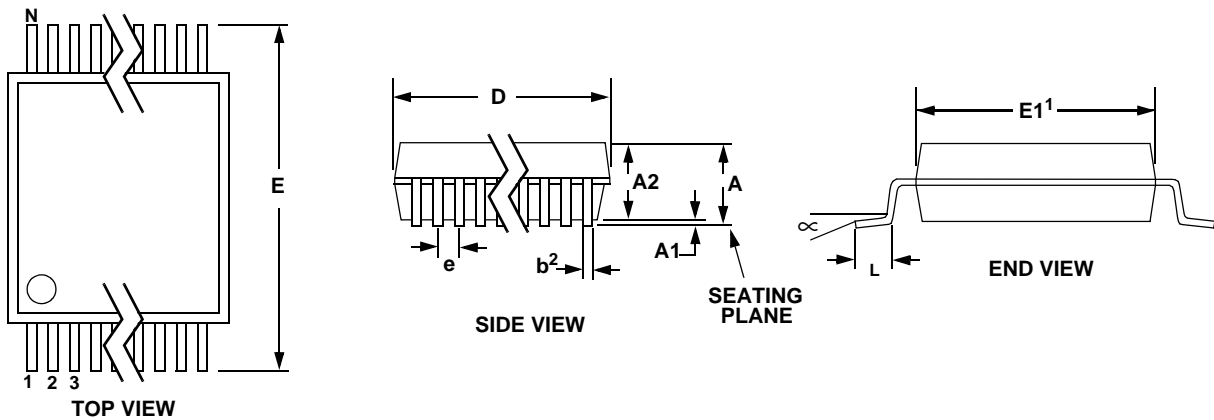
### 8.3 Which E<sup>2</sup>PROMs Can Be Used?

Several industry-standard serial E<sup>2</sup>PROMs that will successfully run auto-boot with the CS5461A are listed below:

- Atmel AT25010, AT25020 or AT25040
- National Semiconductor NM25C040M8 or NM25020M8
- Xicor X25040SI

These types of serial E<sup>2</sup>PROMs expect a specific 8-bit command (00000011) in order to perform a memory read. The CS5461A has been hardware programmed to transmit this 8-bit command to the E<sup>2</sup>PROM at the beginning of the auto-boot sequence.



**10. PACKAGE DIMENSIONS**
**28L SSOP PACKAGE DRAWING**


DIM	INCHES			MILLIMETERS			NOTE
	MIN	NOM	MAX	MIN	NOM	MAX	
A	--	--	0.084	--	--	2.13	
A1	0.002	0.006	0.010	0.05	0.15	0.25	
A2	0.064	0.069	0.074	1.62	1.75	1.88	
b	0.009	--	0.015	0.22	--	0.38	2,3
D	0.390	0.4015	0.413	9.90	10.20	10.50	1
E	0.291	0.307	0.323	7.40	7.80	8.20	
E1	0.197	0.209	0.220	5.00	5.30	5.60	1
e	0.022	0.026	0.030	0.55	0.65	0.75	
L	0.025	0.0354	0.041	0.63	0.90	1.03	
$\infty$	0°	4°	8°	0°	4°	8°	

**JEDEC #: MO-150**

*Controlling Dimension is Millimeters*

- Notes:
1. "D" and "E1" are reference datums and do not include mold flash or protrusions, but do include mold mismatch and are measured at the parting line, mold flash or protrusions shall not exceed 0.20 mm per side.
  2. Dimension "b" does not include dambar protrusion/intrusion. Allowable dambar protrusion shall be 0.13 mm total in excess of "b" dimension at maximum material condition. Dambar intrusion shall not reduce dimension "b" by more than 0.07 mm at least material condition.
  3. These dimensions apply to the flat section of the lead between 0.10 and 0.25 mm from lead tips.

## 11. ORDERING INFORMATION

Model	Temperature	Package
CS5464-IS	-40 to +85 °C	24-pin SSOP
CS5464-ISZ (lead free)		

## 12. ENVIRONMENTAL, MANUFACTURING, & HANDLING INFORMATION

Model Number	Peak Reflow Temp	MSL Rating*	Max Floor Life
CS5464-IS	240 °C	2	365 Days
CS5464-ISZ (lead free)	260 °C	3	7 Days

\* MSL (Moisture Sensitivity Level) as specified by IPC/JEDEC J-STD-020.

### 13. REVISION HISTORY

Revision	Date	Changes
T1	NOV 2005	Target Data Sheet
PP1	MAR 2006	Preliminary Release

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### Contacting Cirrus Logic Support

For all product questions and inquiries contact a Cirrus Logic Sales Representative.

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#### IMPORTANT NOTICE

"Preliminary" product information describes products that are in production, but for which full characterization data is not yet available.

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